

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

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1.0 DEVICE OVERVIEW

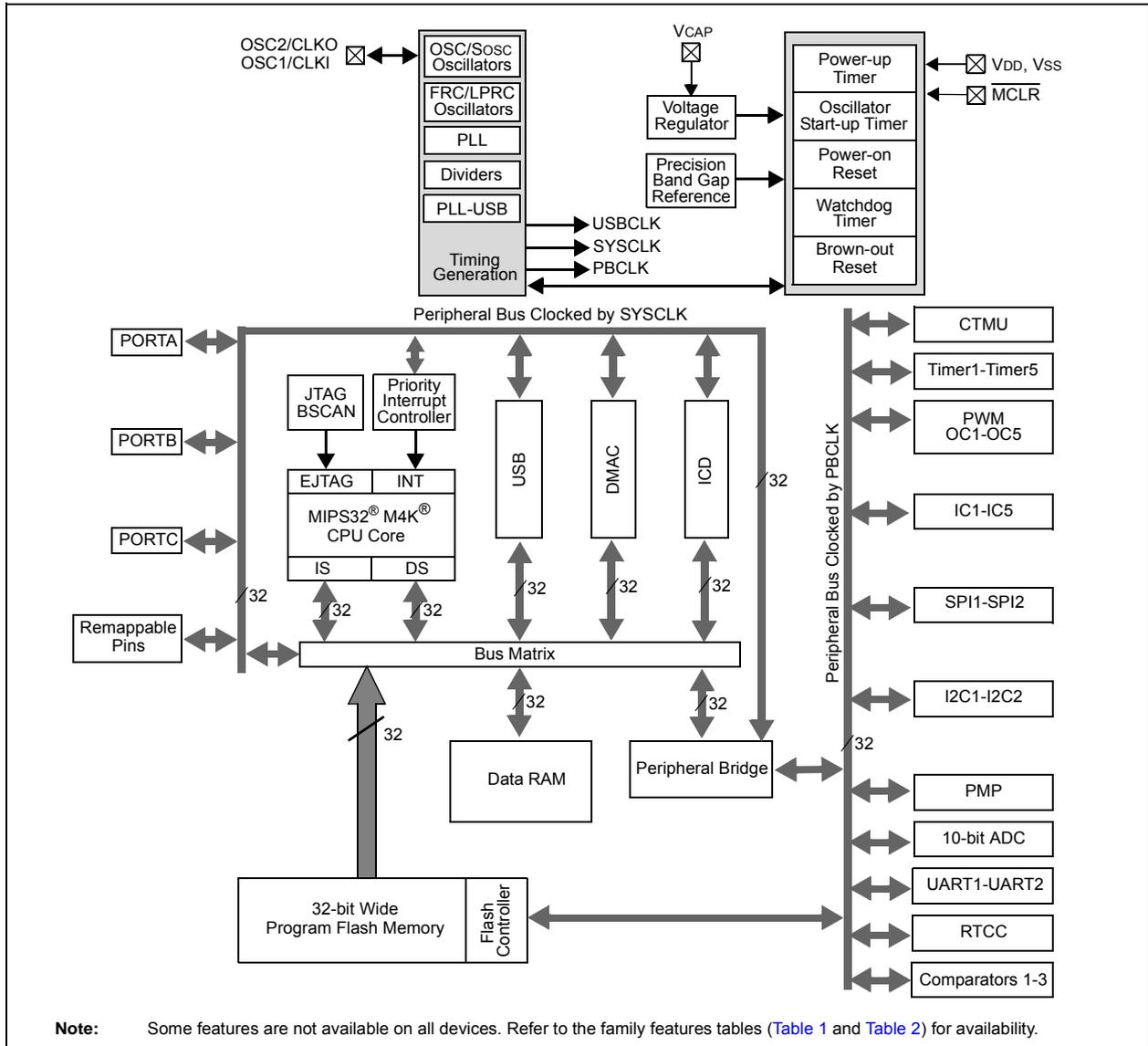
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

This document contains device-specific information for PIC32MX1XX/2XX 28/36/44-pin Family devices.

Figure 1-1 illustrates a general block diagram of the core and peripheral modules in the PIC32MX1XX/2XX 28/36/44-pin Family of devices.

Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: BLOCK DIAGRAM



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REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER

- bit 3 **CF:** Clock Fail Detect bit
 - 1 = FSCM has detected a clock failure
 - 0 = No clock failure has been detected
- bit 2 **UFRGEN:** USB FRC Clock Enable bit⁽¹⁾
 - 1 = Enable the FRC as the clock source for the USB clock source
 - 0 = Use the Primary Oscillator or USB PLL as the USB clock source
- bit 1 **SOSCEN:** Secondary Oscillator (SOSC) Enable bit
 - 1 = Enable the Secondary Oscillator
 - 0 = Disable the Secondary Oscillator
- bit 0 **OSWEN:** Oscillator Switch Enable bit
 - 1 = Initiate an oscillator switch to selection specified by NOSC<2:0> bits
 - 0 = Oscillator switch is complete

Note 1: This bit is only available on PIC32MX2XX devices.

Note: Writes to this register require an unlock sequence. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

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REGISTER 8-3: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

bit 3-0 **ROSEL<3:0>**: Reference Clock Source Select bits⁽¹⁾

1111 = Reserved; do not use

•
•
•

1001 = Reserved; do not use

1000 = REFCLKI

0111 = System PLL output

0110 = USB PLL output

0101 = Sosc

0100 = LPRC

0011 = FRC

0010 = Posc

0001 = PBCLK

0000 = SYSCLK

Note 1: The ROSEL and RODIV bits should not be written while the ACTIVE bit is '1', as undefined behavior may result.

2: This bit is ignored when the ROSEL<3:0> bits = 0000 or 0001.

3: While the ON bit is set to '1', writes to these bits do not take effect until the DIVSWEN bit is also set to '1'.

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REGISTER 9-9: DCHxINT: DMA CHANNEL 'x' INTERRUPT CONTROL REGISTER (CONTINUED)

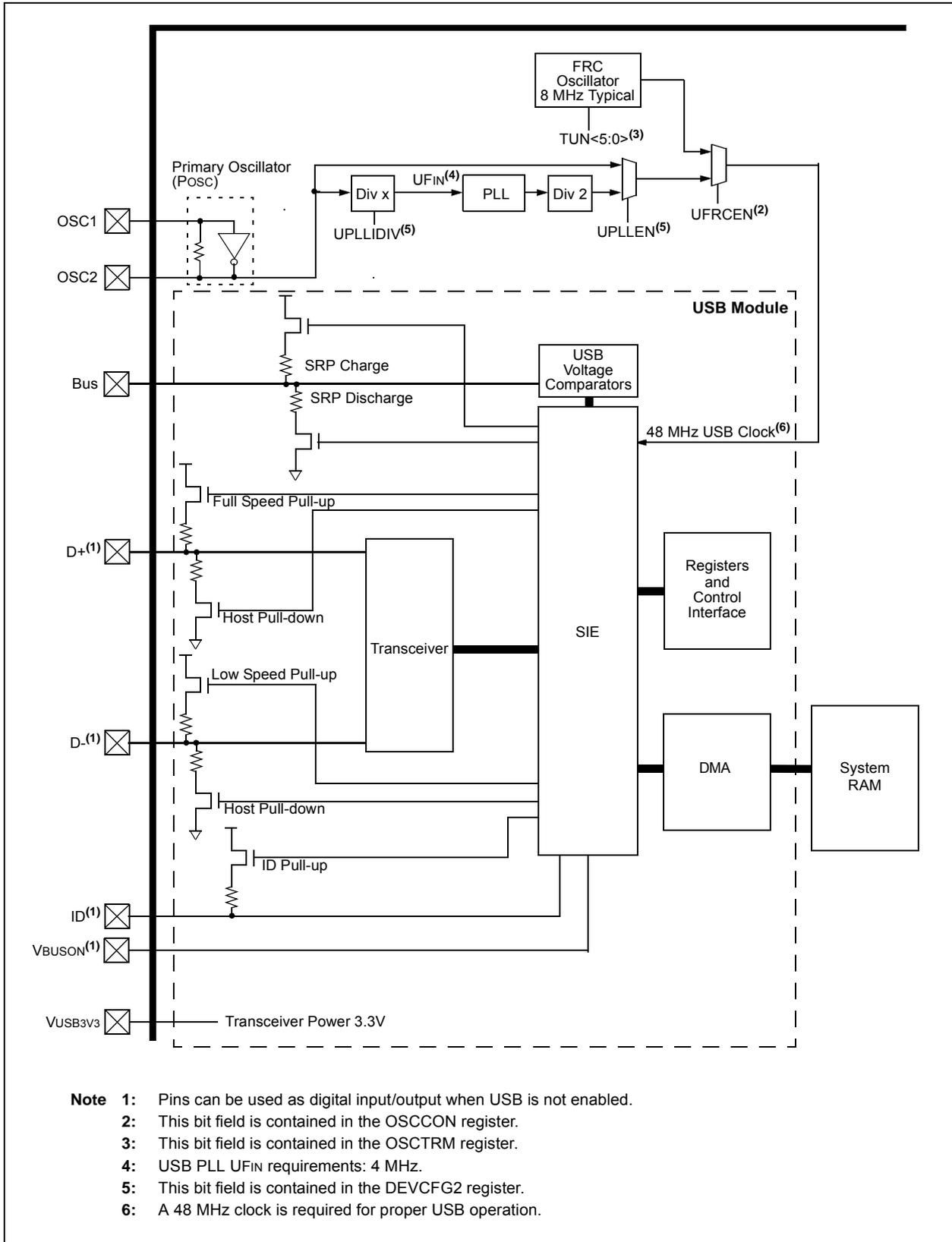
- bit 4 **CHDHIF:** Channel Destination Half Full Interrupt Flag bit
1 = Channel Destination Pointer has reached midpoint of destination (CHDPTR = CHDSIZ/2)
0 = No interrupt is pending
- bit 3 **CHBCIF:** Channel Block Transfer Complete Interrupt Flag bit
1 = A block transfer has been completed (the larger of CHSSIZ/CHDSIZ bytes has been transferred), or a pattern match event occurs
0 = No interrupt is pending
- bit 2 **CHCCIF:** Channel Cell Transfer Complete Interrupt Flag bit
1 = A cell transfer has been completed (CHCSIZ bytes have been transferred)
0 = No interrupt is pending
- bit 1 **CHTAIF:** Channel Transfer Abort Interrupt Flag bit
1 = An interrupt matching CHAIRQ has been detected and the DMA transfer has been aborted
0 = No interrupt is pending
- bit 0 **CHERIF:** Channel Address Error Interrupt Flag bit
1 = A channel address error has been detected (either the source or the destination address is invalid)
0 = No interrupt is pending

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FIGURE 10-1: PIC32MX1XX/2XX 28/36/44-PIN FAMILY FAMILY USB INTERFACE DIAGRAM



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REGISTER 10-8: U1EIR: USB ERROR INTERRUPT STATUS REGISTER (CONTINUED)

bit 1 **CRC5EF:** CRC5 Host Error Flag bit⁽⁴⁾
1 = Token packet rejected due to CRC5 error
0 = Token packet accepted

EOFEF: EOF Error Flag bit^(3,5)
1 = An EOF error condition was detected
0 = No EOF error condition was detected

bit 0 **PIDEF:** PID Check Failure Flag bit
1 = PID check failed
0 = PID check passed

- Note 1:** This type of error occurs when the module's request for the DMA bus is not granted in time to service the module's demand for memory, resulting in an overflow or underflow condition, and/or the allocated buffer size is not sufficient to store the received data packet causing it to be truncated.
- 2:** This type of error occurs when more than 16-bit-times of Idle from the previous End-of-Packet (EOP) has elapsed.
- 3:** This type of error occurs when the module is transmitting or receiving data and the SOF counter has reached zero.
- 4:** Device mode.
- 5:** Host mode.

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REGISTER 10-11: U1CON: USB CONTROL REGISTER (CONTINUED)

- bit 1 **PPBRST:** Ping-Pong Buffers Reset bit
1 = Reset all Even/Odd buffer pointers to the EVEN Buffer Descriptor banks
0 = Even/Odd buffer pointers are not Reset
- bit 0 **USBEN:** USB Module Enable bit⁽⁴⁾
1 = USB module and supporting circuitry is enabled
0 = USB module and supporting circuitry is disabled
- SOFEN:** SOF Enable bit⁽⁵⁾
1 = SOF token is sent every 1 ms
0 = SOF token is disabled

- Note 1:** Software is required to check this bit before issuing another token command to the U1TOK register (see [Register 10-15](#)).
- 2:** All host control logic is reset any time that the value of this bit is toggled.
- 3:** Software must set RESUME for 10 ms if the part is a function, or for 25 ms if the part is a host, and then clear it to enable remote wake-up. In Host mode, the USB module will append a Low-Speed EOP to the RESUME signaling when this bit is cleared.
- 4:** Device mode.
- 5:** Host mode.

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REGISTER 12-1: T1CON: TYPE A TIMER CONTROL REGISTER (CONTINUED)

- bit 3 **Unimplemented:** Read as '0'
- bit 2 **TSYNC:** Timer External Clock Input Synchronization Selection bit
 When TCS = 1:
 1 = External clock input is synchronized
 0 = External clock input is not synchronized
 When TCS = 0:
 This bit is ignored.
- bit 1 **TCS:** Timer Clock Source Select bit
 1 = External clock from TxCKI pin
 0 = Internal peripheral clock
- bit 0 **Unimplemented:** Read as '0'

Note 1: When using 1:1 PBCmLK divisor, the user's software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

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REGISTER 15-1: ICxCON: INPUT CAPTURE 'x' CONTROL REGISTER (CONTINUED)

bit 2-0 **ICM<2:0>**: Input Capture Mode Select bits

- 111 = Interrupt-Only mode (only supported while in Sleep mode or Idle mode)
- 110 = Simple Capture Event mode – every edge, specified edge first and every edge thereafter
- 101 = Prescaled Capture Event mode – every sixteenth rising edge
- 100 = Prescaled Capture Event mode – every fourth rising edge
- 011 = Simple Capture Event mode – every rising edge
- 010 = Simple Capture Event mode – every falling edge
- 001 = Edge Detect mode – every edge (rising and falling)
- 000 = Input Capture module is disabled

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

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REGISTER 18-2: I2CxSTAT: I²C STATUS REGISTER (CONTINUED)

- bit 4 **P:** Stop bit
1 = Indicates that a Stop bit has been detected last
0 = Stop bit was not detected last
Hardware set or clear when Start, Repeated Start or Stop detected.
- bit 3 **S:** Start bit
1 = Indicates that a Start (or Repeated Start) bit has been detected last
0 = Start bit was not detected last
Hardware set or clear when Start, Repeated Start or Stop detected.
- bit 2 **R_W:** Read/Write Information bit (when operating as I²C slave)
1 = Read – indicates data transfer is output from slave
0 = Write – indicates data transfer is input to slave
Hardware set or clear after reception of I²C device address byte.
- bit 1 **RBF:** Receive Buffer Full Status bit
1 = Receive complete, I2CxRCV is full
0 = Receive not complete, I2CxRCV is empty
Hardware set when I2CxRCV is written with received byte. Hardware clear when software reads I2CxRCV.
- bit 0 **TBF:** Transmit Buffer Full Status bit
1 = Transmit in progress, I2CxTRN is full
0 = Transmit complete, I2CxTRN is empty
Hardware set when software writes I2CxTRN. Hardware clear at completion of data transmission.

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REGISTER 19-1: UxMODE: UARTx MODE REGISTER (CONTINUED)

- bit 5 **ABAUD**: Auto-Baud Enable bit
1 = Enable baud rate measurement on the next character – requires reception of Sync character (0x55); cleared by hardware upon completion
0 = Baud rate measurement disabled or completed
- bit 4 **RXINV**: Receive Polarity Inversion bit
1 = UxRX Idle state is '0'
0 = UxRX Idle state is '1'
- bit 3 **BRGH**: High Baud Rate Enable bit
1 = High-Speed mode – 4x baud clock enabled
0 = Standard Speed mode – 16x baud clock enabled
- bit 2-1 **PDSEL<1:0>**: Parity and Data Selection bits
11 = 9-bit data, no parity
10 = 8-bit data, odd parity
01 = 8-bit data, even parity
00 = 8-bit data, no parity
- bit 0 **STSEL**: Stop Selection bit
1 = 2 Stop bits
0 = 1 Stop bit

Note 1: When using 1:1 PBCLK divisor, the user software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

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REGISTER 20-2: PPMODE: PARALLEL PORT MODE REGISTER (CONTINUED)

bit 1-0 **WAITE<1:0>**: Data Hold After Read/Write Strobe Wait States bits⁽¹⁾

- 11 = Wait of 4 TPB
- 10 = Wait of 3 TPB
- 01 = Wait of 2 TPB
- 00 = Wait of 1 TPB (default)

For Read operations:

- 11 = Wait of 3 TPB
- 10 = Wait of 2 TPB
- 01 = Wait of 1 TPB
- 00 = Wait of 0 TPB (default)

Note 1: Whenever WAITM<3:0> = 0000, WAITB and WAITE bits are ignored and forced to 1 TPBCLK cycle for a write operation; WAITB = 1 TPBCLK cycle, WAITE = 0 TPBCLK cycles for a read operation.

2: Address bit A14 is not subject to auto-increment/decrement if configured as Chip Select CS1.

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REGISTER 21-1: RTCCON: RTC CONTROL REGISTER (CONTINUED)

- bit 5-4 **Unimplemented:** Read as '0'
- bit 3 **RTCWREN:** RTC Value Registers Write Enable bit⁽⁴⁾
1 = RTC Value registers can be written to by the user
0 = RTC Value registers are locked out from being written to by the user
- bit 2 **RTCSYNC:** RTCC Value Registers Read Synchronization bit
1 = RTC Value registers can change while reading, due to a rollover ripple that results in an invalid data read
 If the register is read twice and results in the same data, the data can be assumed to be valid
0 = RTC Value registers can be read without concern about a rollover ripple
- bit 1 **HALFSEC:** Half-Second Status bit⁽⁵⁾
1 = Second half period of a second
0 = First half period of a second
- bit 0 **RTCOE:** RTCC Output Enable bit
1 = RTCC clock output enabled – clock presented onto an I/O
0 = RTCC clock output disabled

- Note 1:** The ON bit is only writable when RTCWREN = 1.
- 2:** When using the 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.
- 3:** Requires RTCOE = 1 (RTCCON<0>) for the output to be active.
- 4:** The RTCWREN bit can be set only when the write sequence is enabled.
- 5:** This bit is read-only. It is cleared to '0' on a write to the seconds bit fields (RTCTIME<14:8>).

Note: This register is reset only on a Power-on Reset (POR).

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REGISTER 21-2: RTCALRM: RTC ALARM CONTROL REGISTER (CONTINUED)

bit 7-0 **ARPT<7:0>**: Alarm Repeat Counter Value bits⁽²⁾

11111111 = Alarm will trigger 256 times

.

.

00000000 = Alarm will trigger one time

The counter decrements on any alarm event. The counter only rolls over from 0x00 to 0xFF if CHIME = 1.

- Note 1:** Hardware clears the ALRMEN bit anytime the alarm event occurs, when ARPT<7:0> = 00 and CHIME = 0.
- 2:** This field should not be written when the RTCC ON bit = '1' (RTCCON<15>) and ALRMSYNC = 1.
- 3:** This assumes a CPU read will execute in less than 32 PBCLKs.

Note: This register is reset only on a Power-on Reset (POR).

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FIGURE 22-2: ADC CONVERSION CLOCK PERIOD BLOCK DIAGRAM

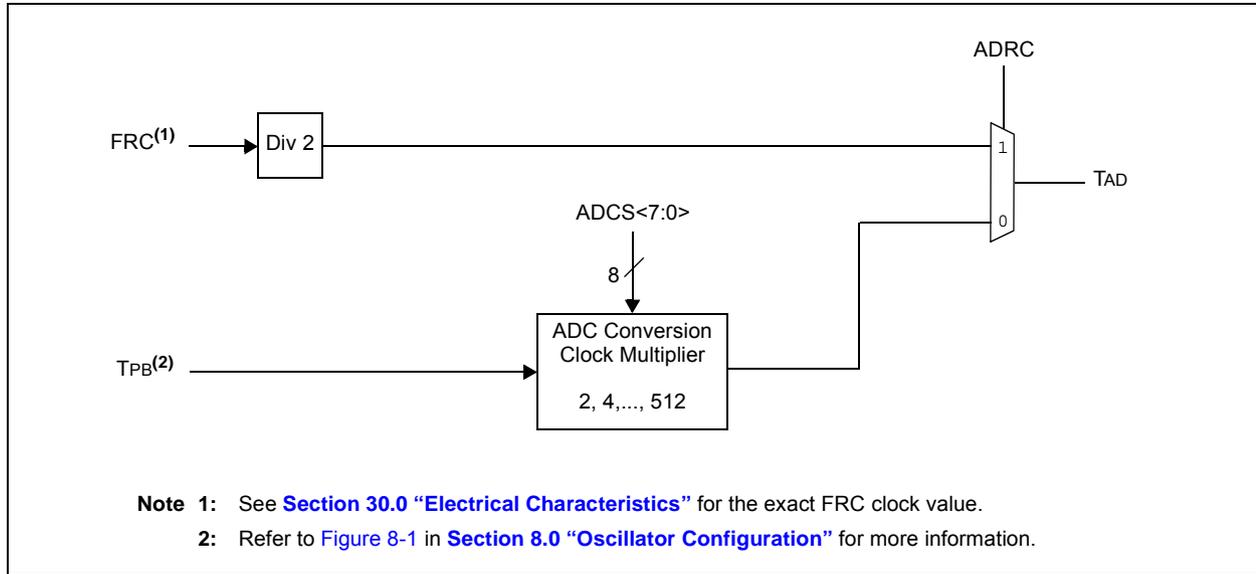


TABLE 22-1: ADC REGISTER MAP (CONTINUED)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits														All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	
9120	ADC1BUF B	31:16	ADC Result Word B (ADC1BUF B<31:0>)														0000
		15:0															0000
9130	ADC1BUF C	31:16	ADC Result Word C (ADC1BUF C<31:0>)														0000
		15:0															0000
9140	ADC1BUF D	31:16	ADC Result Word D (ADC1BUF D<31:0>)														0000
		15:0															0000
9150	ADC1BUF E	31:16	ADC Result Word E (ADC1BUF E<31:0>)														0000
		15:0															0000
9160	ADC1BUF F	31:16	ADC Result Word F (ADC1BUF F<31:0>)														0000
		15:0															0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus offsets of 0x4, 0x8 and 0xC, respectively. See [Section 11.2 "CLR, SET and INV Registers"](#) for details.

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REGISTER 22-1: AD1CON1: ADC CONTROL REGISTER 1 (CONTINUED)

- bit 4 **CLRASAM:** Stop Conversion Sequence bit (when the first ADC interrupt is generated)
1 = Stop conversions when the first ADC interrupt is generated. Hardware clears the ASAM bit when the ADC interrupt is generated.
0 = Normal operation, buffer contents will be overwritten by the next conversion sequence
- bit 3 **Unimplemented:** Read as '0'
- bit 2 **ASAM:** ADC Sample Auto-Start bit
1 = Sampling begins immediately after last conversion completes; SAMP bit is automatically set.
0 = Sampling begins when SAMP bit is set
- bit 1 **SAMP:** ADC Sample Enable bit⁽²⁾
1 = The ADC sample and hold amplifier is sampling
0 = The ADC sample/hold amplifier is holding
When ASAM = 0, writing '1' to this bit starts sampling.
When SSRC = 000, writing '0' to this bit will end sampling and start conversion.
- bit 0 **DONE:** Analog-to-Digital Conversion Status bit⁽³⁾
1 = Analog-to-digital conversion is done
0 = Analog-to-digital conversion is not done or has not started
Clearing this bit will not affect any operation in progress.

- Note 1:** When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.
- 2:** If ASAM = 0, software can write a '1' to start sampling. This bit is automatically set by hardware if ASAM = 1. If SSRC = 0, software can write a '0' to end sampling and start conversion. If SSRC ≠ '0', this bit is automatically cleared by hardware to end sampling and start conversion.
- 3:** This bit is automatically set by hardware when analog-to-digital conversion is complete. Software can write a '0' to clear this bit (a write of '1' is not allowed). Clearing this bit does not affect any operation already in progress. This bit is automatically cleared by hardware at the start of a new conversion.

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23.0 COMPARATOR

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 19. “Comparator”** (DS60001110), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

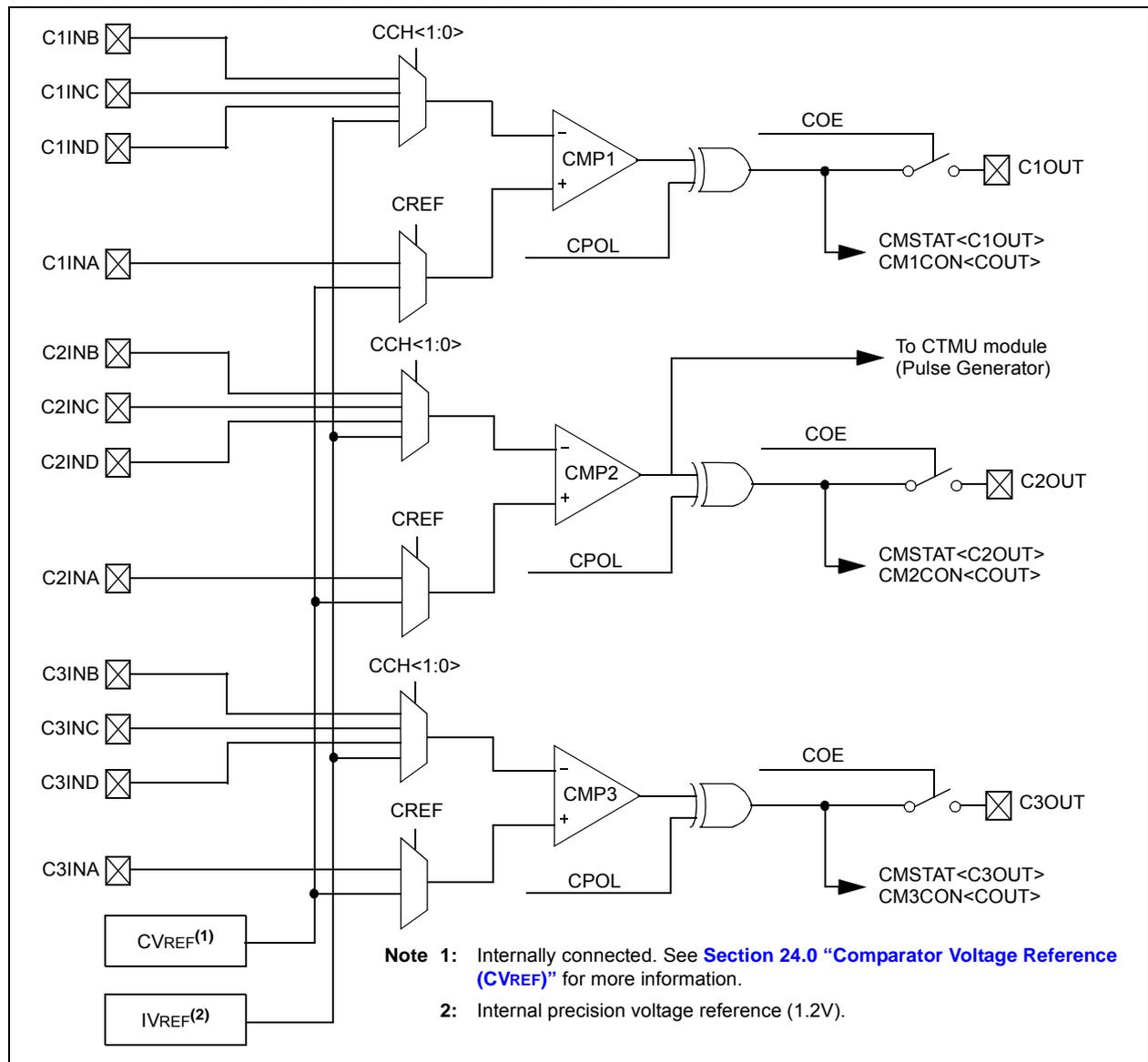
Following are some of the key features of this module:

- Selectable inputs available include:
 - Analog inputs multiplexed with I/O pins
 - On-chip internal absolute voltage reference (IVREF)
 - Comparator voltage reference (CVREF)
- Outputs can be Inverted
- Selectable interrupt generation

A block diagram of the comparator module is provided in [Figure 23-1](#).

The Analog Comparator module contains three comparators that can be configured in a variety of ways.

FIGURE 23-1: COMPARATOR BLOCK DIAGRAM



23.1 Comparator Control Registers

TABLE 23-1: COMPARATOR REGISTER MAP

Virtual Address (BF80_#)	Register Name ⁽¹⁾	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	
A000	CM1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	COE	CPOL	—	—	—	—	COUT	EVPOL<1:0>	—	CREF	—	—	—	CCH<1:0>	00C3
A010	CM2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	COE	CPOL	—	—	—	—	COUT	EVPOL<1:0>	—	CREF	—	—	—	CCH<1:0>	00C3
A020	CM3CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	COE	CPOL	—	—	—	—	COUT	EVPOL<1:0>	—	CREF	—	—	—	CCH<1:0>	00C3
A060	CMSTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	SIDL	—	—	—	—	—	—	—	—	—	—	C3OUT	C2OUT	C1OUT

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See [Section 11.2 “CLR, SET and INV Registers”](#) for more information.

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24.0 COMPARATOR VOLTAGE REFERENCE (CVREF)

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 20. “Comparator Voltage Reference (CVREF)”** (DS60001109), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The CVREF module is a 16-tap, resistor ladder network that provides a selectable reference voltage. Although its primary purpose is to provide a reference for the analog comparators, it also may be used independently of them.

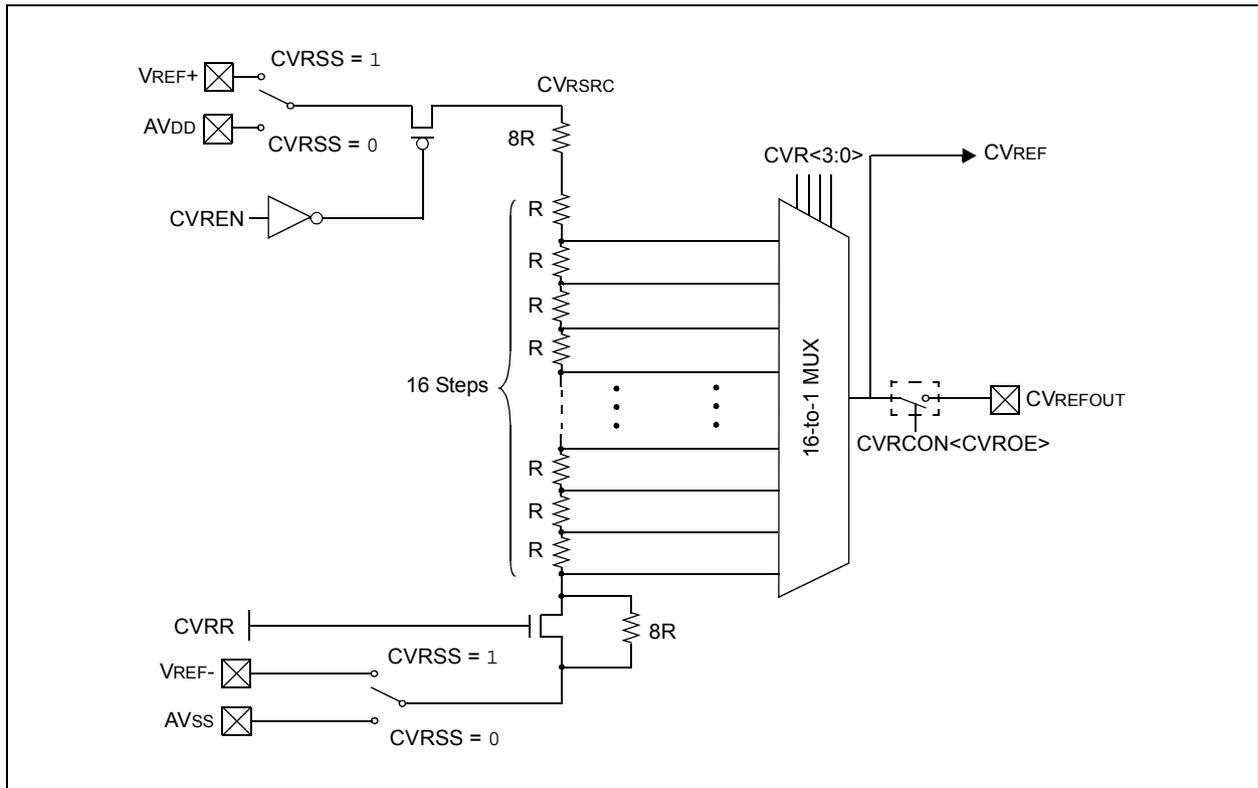
The resistor ladder is segmented to provide two ranges of voltage reference values and has a power-down function to conserve power when the reference is not being used. The module’s supply reference can be provided from either device VDD/VSS or an external voltage reference. The CVREF output is available for the comparators and typically available for pin output.

The comparator voltage reference has the following features:

- High and low range selection
- Sixteen output levels available for each range
- Internally connected to comparators to conserve device pins
- Output can be connected to a pin

A block diagram of the module is shown in [Figure 24-1](#).

FIGURE 24-1: COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM



24.1 Comparator Voltage Reference Control Register

TABLE 24-1: COMPARATOR VOLTAGE REFERENCE REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	
9800	CVRCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	—	—	—	—	—	—	—	CVROE	CVRR	CVRSS	CVR<3:0>			0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See [Section 11.2 "CLR, SET and INV Registers"](#) for more information.

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25.0 CHARGE TIME MEASUREMENT UNIT (CTMU)

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 37. “Charge Time Measurement Unit (CTMU)”** (DS60001167), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

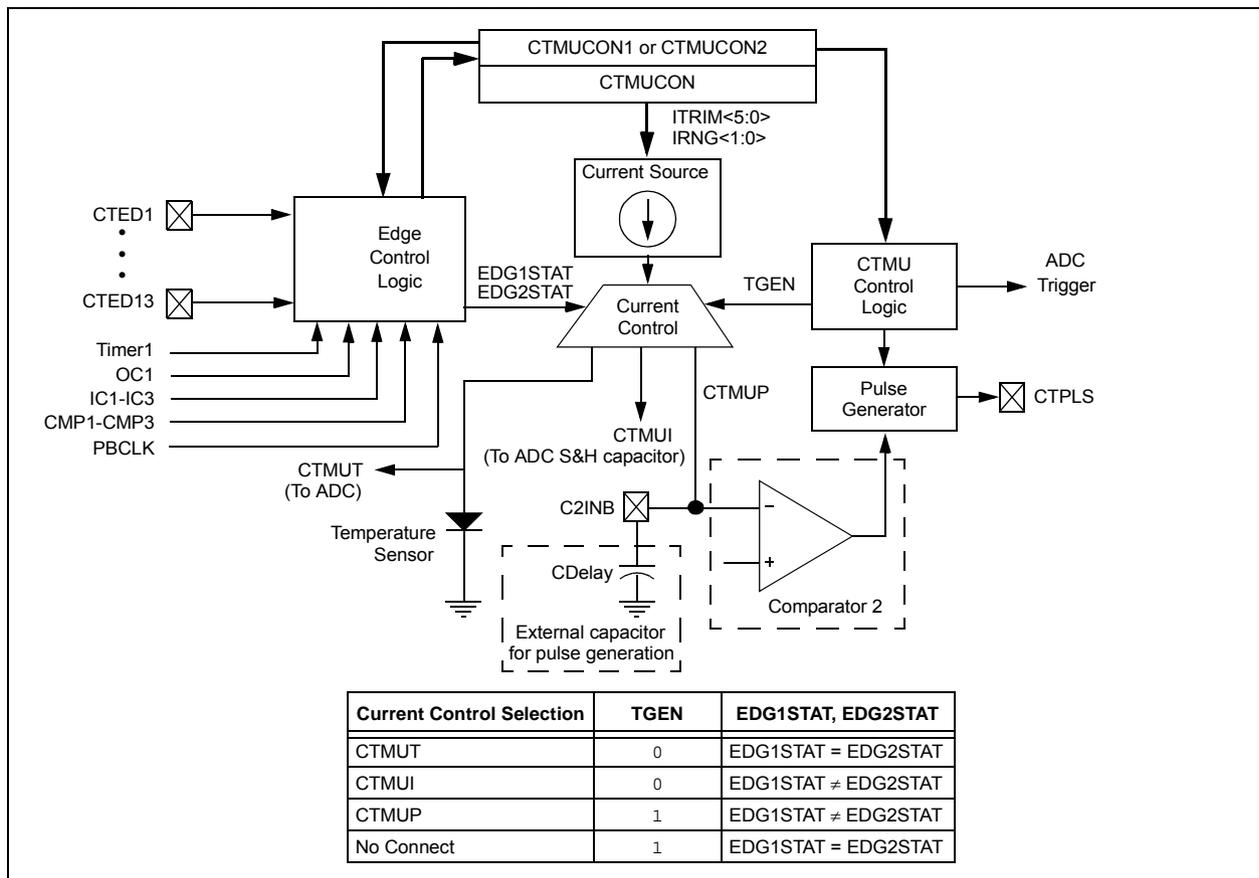
The Charge Time Measurement Unit (CTMU) is a flexible analog module that has a configurable current source with a digital configuration circuit built around it. The CTMU can be used for differential time measurement between pulse sources and can be used for generating an asynchronous pulse. By working with other on-chip analog modules, the CTMU can be used for high resolution time measurement, measure capacitance, measure relative changes in capacitance or generate output pulses with a specific time delay. The CTMU is ideal for interfacing with capacitive-based sensors.

The CTMU module includes the following key features:

- Up to 13 channels available for capacitive or time measurement input
- On-chip precision current source
- 16-edge input trigger sources
- Selection of edge or level-sensitive inputs
- Polarity control for each edge source
- Control of edge sequence
- Control of response to edges
- High precision time measurement
- Time delay of external or internal signal asynchronous to system clock
- Integrated temperature sensing diode
- Control of current source during auto-sampling
- Four current source ranges
- Time measurement resolution of one nanosecond

A block diagram of the CTMU is shown in [Figure 25-1](#).

FIGURE 25-1: CTMU BLOCK DIAGRAM



25.1 CTMU Control Registers

TABLE 25-1: CTMU REGISTER MAP

Virtual Address (BF80_#)	Register Name ⁽¹⁾	Bit Range	Bits														All Resets	
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2		17/1
A200	CTMUCON	31:16	EDG1MOD	EDG1POL	EDG1SEL<3:0>				EDG2STAT	EDG1STAT	EDG2MOD	EDG2POL	EDG2SEL<3:0>			—	—	0000
		15:0	ON	—	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN	CTTRIG	ITRIM<5:0>					IRNG<1:0>		0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See [Section 11.2 "CLR, SET and INV Registers"](#) for more information.

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REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

- bit 24 **EDG1STAT:** Edge1 Status bit
Indicates the status of Edge1 and can be written to control edge source
1 = Edge1 has occurred
0 = Edge1 has not occurred
- bit 23 **EDG2MOD:** Edge2 Edge Sampling Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive
- bit 22 **EDG2POL:** Edge 2 Polarity Select bit
1 = Edge2 programmed for a positive edge response
0 = Edge2 programmed for a negative edge response
- bit 21-18 **EDG2SEL<3:0>:** Edge 2 Source Select bits
1111 = C3OUT pin is selected
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = PBCLK clock is selected
1011 = IC3 Capture Event is selected
1010 = IC2 Capture Event is selected
1001 = IC1 Capture Event is selected
1000 = CTED13 pin is selected
0111 = CTED12 pin is selected
0110 = CTED11 pin is selected
0101 = CTED10 pin is selected
0100 = CTED9 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected
- bit 17-16 **Unimplemented:** Read as '0'
- bit 15 **ON:** ON Enable bit
1 = Module is enabled
0 = Module is disabled
- bit 14 **Unimplemented:** Read as '0'
- bit 13 **CTMUSIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when the device enters Idle mode
0 = Continue module operation when the device enters Idle mode
- bit 12 **TGEN:** Time Generation Enable bit⁽¹⁾
1 = Enables edge delay generation
0 = Disables edge delay generation
- bit 11 **EDGEN:** Edge Enable bit
1 = Edges are not blocked
0 = Edges are blocked

- Note 1:** When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.
- 2:** The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.
- 3:** Refer to the CTMU Current Source Specifications (Table 30-41) in [Section 30.0 "Electrical Characteristics"](#) for current values.
- 4:** This bit setting is not available for the CTMU temperature diode.

REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

- bit 10 **EDGSEQEN**: Edge Sequence Enable bit
1 = Edge1 must occur before Edge2 can occur
0 = No edge sequence is needed
- bit 9 **IDISSEN**: Analog Current Source Control bit⁽²⁾
1 = Analog current source output is grounded
0 = Analog current source output is not grounded
- bit 8 **CTTRIG**: Trigger Control bit
1 = Trigger output is enabled
0 = Trigger output is disabled
- bit 7-2 **ITRIM<5:0>**: Current Source Trim bits
011111 = Maximum positive change from nominal current
011110
.
.
.
000001 = Minimum positive change from nominal current
000000 = Nominal current output specified by IRNG<1:0>
111111 = Minimum negative change from nominal current
.
.
.
100010
100001 = Maximum negative change from nominal current
- bit 1-0 **IRNG<1:0>**: Current Range Select bits⁽³⁾
11 = 100 times base current
10 = 10 times base current
01 = Base current level
00 = 1000 times base current⁽⁴⁾

- Note 1:** When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.
- 2:** The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.
- 3:** Refer to the CTMU Current Source Specifications (Table 30-41) in Section 30.0 "Electrical Characteristics" for current values.
- 4:** This bit setting is not available for the CTMU temperature diode.

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26.4.1 CONTROLLING CONFIGURATION CHANGES

Because peripherals can be disabled during run time, some restrictions on disabling peripherals are needed to prevent accidental configuration changes. PIC32 devices include two features to prevent alterations to enabled or disabled peripherals:

- Control register lock sequence
- Configuration bit select lock

26.4.1.1 Control Register Lock

Under normal operation, writes to the PMDx registers are not allowed. Attempted writes appear to execute normally, but the contents of the registers remain unchanged. To change these registers, they must be unlocked in hardware. The register lock is controlled by the Configuration bit, PMDLOCK (CFGCON<12>). Setting PMDLOCK prevents writes to the control registers; clearing PMDLOCK allows writes.

To set or clear PMDLOCK, an unlock sequence must be executed. Refer to **Section 6. “Oscillator”** (DS60001112) in the *“PIC32 Family Reference Manual”* for details.

26.4.1.2 Configuration Bit Select Lock

As an additional level of safety, the device can be configured to prevent more than one write session to the PMDx registers. The Configuration bit, PMDL1WAY (DEVCFG3<28>), blocks the PMDLOCK bit from being cleared after it has been set once. If PMDLOCK remains set, the register unlock procedure does not execute, and the peripheral pin select control registers cannot be written to. The only way to clear the bit and re-enable PMD functionality is to perform a device Reset.

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27.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 32. “Configuration”** (DS60001124) and **Section 33. “Programming and Diagnostics”** (DS60001129), which are available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

PIC32MX1XX/2XX 28/36/44-pin Family devices include the following features intended to maximize application flexibility, reliability and minimize cost through elimination of external components.

- Flexible device configuration
- Joint Test Action Group (JTAG) interface
- In-Circuit Serial Programming™ (ICSP™)

27.1 Configuration Bits

The Configuration bits can be programmed using the following registers to select various device configurations.

- [DEVCFG0: Device Configuration Word 0](#)
- [DEVCFG1: Device Configuration Word 1](#)
- [DEVCFG2: Device Configuration Word 2](#)
- [DEVCFG3: Device Configuration Word 3](#)
- [CFGCON: Configuration Control Register](#)

In addition, the DEVID register ([Register 27-6](#)) provides device and revision information.

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REGISTER 27-1: DEVCFG0: DEVICE CONFIGURATION WORD 0

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-0	r-1	r-1	R/P	r-1	r-1	r-1	R/P
	—	—	—	CP	—	—	—	BWP
23:16	r-1	r-1	r-1	r-1	r-1	R/P	R/P	R/P
	—	—	—	—	—	PWP<8:6> ⁽³⁾		
15:8	R/P	R/P	R/P	R/P	R/P	R/P	r-1	r-1
	PWP<5:0>							—
7:0	r-1	r-1	r-1	R/P	R/P	R/P	R/P	R/P
	—	—	—	ICESEL<1:0> ⁽²⁾		JTAGEN ⁽¹⁾	DEBUG<1:0>	

Legend:	r = Reserved bit	P = Programmable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **Reserved:** Write '0'

bit 30-29 **Reserved:** Write '1'

bit 28 **CP:** Code-Protect bit

Prevents boot and program Flash memory from being read or modified by an external programming device.

1 = Protection is disabled

0 = Protection is enabled

bit 27-25 **Reserved:** Write '1'

bit 24 **BWP:** Boot Flash Write-Protect bit

Prevents boot Flash memory from being modified during code execution.

1 = Boot Flash is writable

0 = Boot Flash is not writable

bit 23-19 **Reserved:** Write '1'

Note 1: This bit sets the value for the JTAGEN bit in the CFGCON register.

2: The PGEC4/PGED4 pin pair is not available on all devices. Refer to the [“Pin Diagrams”](#) section for availability.

3: The PWP<8:7> bits are only available on devices with 256 KB Flash.

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REGISTER 27-2: DEVCFG1: DEVICE CONFIGURATION WORD 1 (CONTINUED)

- bit 15-14 **FCKSM<1:0>**: Clock Switching and Monitor Selection Configuration bits
1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled
01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled
00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled
- bit 13-12 **FPBDIV<1:0>**: Peripheral Bus Clock Divisor Default Value bits
11 = PBCLK is SYSCLK divided by 8
10 = PBCLK is SYSCLK divided by 4
01 = PBCLK is SYSCLK divided by 2
00 = PBCLK is SYSCLK divided by 1
- bit 11 **Reserved**: Write '1'
- bit 10 **OSCIOfNC**: CLKO Enable Configuration bit
1 = CLKO output disabled
0 = CLKO output signal active on the OSCO pin; Primary Oscillator must be disabled or configured for the External Clock mode (EC) for the CLKO to be active (POSCMOD<1:0> = 11 or 00)
- bit 9-8 **POSCMOD<1:0>**: Primary Oscillator Configuration bits
11 = Primary Oscillator is disabled
10 = HS Oscillator mode is selected
01 = XT Oscillator mode is selected
00 = External Clock mode is selected
- bit 7 **IESO**: Internal External Switchover bit
1 = Internal External Switchover mode is enabled (Two-Speed Start-up is enabled)
0 = Internal External Switchover mode is disabled (Two-Speed Start-up is disabled)
- bit 6 **Reserved**: Write '1'
- bit 5 **FSOSCEN**: Secondary Oscillator Enable bit
1 = Enable Secondary Oscillator
0 = Disable Secondary Oscillator
- bit 4-3 **Reserved**: Write '1'
- bit 2-0 **FNOSC<2:0>**: Oscillator Selection bits
111 = Fast RC Oscillator with divide-by-N (FRCDIV)
110 = FRCDIV16 Fast RC Oscillator with fixed divide-by-16 postscaler
101 = Low-Power RC Oscillator (LPRC)
100 = Secondary Oscillator (Sosc)
011 = Primary Oscillator (Posc) with PLL module (XT+PLL, HS+PLL, EC+PLL)
010 = Primary Oscillator (XT, HS, EC)⁽¹⁾
001 = Fast RC Oscillator with divide-by-N with PLL module (FRCDIV+PLL)
000 = Fast RC Oscillator (FRC)

Note 1: Do not disable the Posc (POSCMOD = 11) when using this oscillator source.

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REGISTER 27-3: DEVCFG2: DEVICE CONFIGURATION WORD 2 (CONTINUED)

bit 2-0 **FPLLIDIV<2:0>**: PLL Input Divider bits

111 = 12x divider

110 = 10x divider

101 = 6x divider

100 = 5x divider

011 = 4x divider

010 = 3x divider

001 = 2x divider

000 = 1x divider

Note 1: This bit is only available on PIC32MX2XX devices.

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REGISTER 27-6: DEVID: DEVICE AND REVISION ID REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R	R	R	R	R	R	R	R
	VER<3:0> ⁽¹⁾				DEVID<27:24> ⁽¹⁾			
23:16	R	R	R	R	R	R	R	R
	DEVID<23:16> ⁽¹⁾							
15:8	R	R	R	R	R	R	R	R
	DEVID<15:8> ⁽¹⁾							
7:0	R	R	R	R	R	R	R	R
	DEVID<7:0> ⁽¹⁾							

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown

bit 31-28 **VER<3:0>**: Revision Identifier bits⁽¹⁾

bit 27-0 **DEVID<27:0>**: Device ID bits⁽¹⁾

Note 1: See the “PIC32 Flash Programming Specification” (DS60001145) for a list of Revision and Device ID values.

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28.0 INSTRUCTION SET

The PIC32MX1XX/2XX family instruction set complies with the MIPS32[®] Release 2 instruction set architecture. The PIC32 device family does not support the following features:

- Core extend instructions
- Coprocessor 1 instructions
- Coprocessor 2 instructions

Note: Refer to “MIPS32[®] Architecture for Programmers Volume II: The MIPS32[®] Instruction Set” at www.imgtec.com for more information.

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29.0 DEVELOPMENT SUPPORT

The PIC[®] microcontrollers (MCU) and dsPIC[®] digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
 - MPLAB[®] X IDE Software
- Compilers/Assemblers/Linkers
 - MPLAB XC Compiler
 - MPASM[™] Assembler
 - MPLINK[™] Object Linker/
MPLIB[™] Object Librarian
 - MPLAB Assembler/Linker/Librarian for
Various Device Families
- Simulators
 - MPLAB X SIM Software Simulator
- Emulators
 - MPLAB REAL ICE[™] In-Circuit Emulator
- In-Circuit Debuggers/Programmers
 - MPLAB ICD 3
 - PICKit[™] 3
- Device Programmers
 - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards,
Evaluation Kits and Starter Kits
- Third-party development tools

29.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows[®], Linux and Mac OS[®] X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

Project-Based Workspaces:

- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

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29.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

29.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

29.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/librarian features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

29.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

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29.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

29.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

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30.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of the PIC32MX1XX/2XX 28/36/44-pin Family electrical characteristics for devices that operate at 40 MHz. Refer to [Section 31.0 “50 MHz Electrical Characteristics”](#) for additional specifications for operations at higher frequency. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the PIC32MX1XX/2XX 28/36/44-pin Family devices are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions, above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings

(See Note 1)

Ambient temperature under bias	-40°C to +105°C
Storage temperature	-65°C to +150°C
Voltage on VDD with respect to VSS	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to VSS (Note 3).....	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 2.3V (Note 3).....	-0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to VSS when VDD < 2.3V (Note 3).....	-0.3V to +3.6V
Voltage on D+ or D- pin with respect to VUSB3V3	-0.3V to (VUSB3V3 + 0.3V)
Voltage on VBUS with respect to VSS	-0.3V to +5.5V
Maximum current out of VSS pin(s)	300 mA
Maximum current into VDD pin(s) (Note 2).....	300 mA
Maximum output current sunk by any I/O pin.....	15 mA
Maximum output current sourced by any I/O pin	15 mA
Maximum current sunk by all ports	200 mA
Maximum current sourced by all ports (Note 2).....	200 mA

Note 1: Stresses above those listed under “**Absolute Maximum Ratings**” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions, above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see [Table 30-2](#)).

3: See the “[Pin Diagrams](#)” section for the 5V tolerant pins.

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TABLE 30-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typ.	Max.	Units	Conditions
Operating Voltage							
DC10	VDD	Supply Voltage (Note 2)	2.3	—	3.6	V	—
DC12	VDR	RAM Data Retention Voltage (Note 1)	1.75	—	—	V	—
DC16	VPOR	VDD Start Voltage to Ensure Internal Power-on Reset Signal	1.75	—	2.1	V	—
DC17	SVDD	VDD Rise Rate to Ensure Internal Power-on Reset Signal	0.00005	—	0.115	V/μs	—

- Note 1:** This is the limit to which VDD can be lowered without losing RAM data.
- 2:** Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in [Table 30-11](#) for BOR values.

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TABLE 30-5: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp	
Parameter No.	Typical ⁽³⁾	Max.	Units	Conditions
Operating Current (IDD) (Notes 1, 2, 5)				
DC20	2	3	mA	4 MHz (Note 4)
DC21	7	10.5	mA	10 MHz
DC22	10	15	mA	20 MHz (Note 4)
DC23	15	23	mA	30 MHz (Note 4)
DC24	20	30	mA	40 MHz
DC25	100	150	µA	+25°C, 3.3V LPRC (31 kHz) (Note 4)

Note 1: A device's IDD supply current is mainly a function of the operating voltage and frequency. Other factors, such as PBCLK (Peripheral Bus Clock) frequency, number of peripheral modules enabled, internal code execution pattern, execution from Program Flash memory vs. SRAM, I/O pin loading and switching rate, oscillator type, as well as temperature, can have an impact on the current consumption.

- 2:** The test conditions for IDD measurements are as follows:
- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
 - OSC2/CLKO is configured as an I/O input pin
 - USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
 - CPU, Program Flash, and SRAM data memory are operational, SRAM data memory Wait states = 1
 - No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is cleared
 - WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
 - All I/O pins are configured as inputs and pulled to Vss
 - MCLR = VDD
 - CPU executing `while(1)` statement from Flash
 - RTCC and JTAG are disabled
- 3:** Data in "Typical" column is at 3.3V, 25°C at specified operating frequency unless otherwise stated. Parameters are for design guidance only and are not tested.
- 4:** This parameter is characterized, but not tested in manufacturing.
- 5:** IPD electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

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TABLE 30-6: DC CHARACTERISTICS: IDLE CURRENT (IDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp			
Parameter No.	Typical ⁽²⁾	Max.	Units	Conditions		
Idle Current (IDLE): Core Off, Clock on Base Current (Notes 1, 4)						
DC30a	1	1.5	mA	4 MHz (Note 3)		
DC31a	2	3	mA	10 MHz		
DC32a	4	6	mA	20 MHz (Note 3)		
DC33a	5.5	8	mA	30 MHz (Note 3)		
DC34a	7.5	11	mA	40 MHz		
DC37a	100	—	μA	-40°C	3.3V	LPRC (31 kHz) (Note 3)
DC37b	250	—	μA	$+25^{\circ}\text{C}$		
DC37c	380	—	μA	$+85^{\circ}\text{C}$		

Note 1: The test conditions for IDLE current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
 - OSC2/CLKO is configured as an I/O input pin
 - USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
 - CPU is in Idle mode (CPU core Halted), and SRAM data memory Wait states = 1
 - No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is cleared
 - WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
 - All I/O pins are configured as inputs and pulled to Vss
 - MCLR = VDD
 - RTCC and JTAG are disabled
- 2:** Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.
- 3:** This parameter is characterized, but not tested in manufacturing.
- 4:** IDLE electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-9: DC CHARACTERISTICS: I/O PIN INPUT INJECTION CURRENT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)				
			Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typ. ⁽¹⁾	Max.	Units	Conditions
DI60a	I _{ICL}	Input Low Injection Current	0	—	-5 ^(2,5)	mA	This parameter applies to all pins, with the exception of the power pins.
DI60b	I _{ICH}	Input High Injection Current	0	—	+5 ^(3,4,5)	mA	This parameter applies to all pins, with the exception of all 5V tolerant pins, and the SOSC1, SOSCO, OSC1, D+, and D- pins.
DI60c	Σ I _{ICT}	Total Input Injection Current (sum of all I/O and Control pins)	-20 ⁽⁶⁾	—	+20 ⁽⁶⁾	mA	Absolute instantaneous sum of all \pm input injection currents from all I/O pins ($ I_{ICL} + I_{ICH} \leq \Sigma I_{ICT}$)

- Note 1:** Data in “Typical” column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.
- 2:** V_{IL} source $< (V_{SS} - 0.3)$. Characterized but not tested.
- 3:** V_{IH} source $> (V_{DD} + 0.3)$ for non-5V tolerant pins only.
- 4:** Digital 5V tolerant pins do not have an internal high side diode to V_{DD} , and therefore, cannot tolerate any “positive” input injection current.
- 5:** Injection currents $> |0|$ can affect the ADC results by approximately 4 to 6 counts (i.e., V_{IH} Source $> (V_{DD} + 0.3)$ or V_{IL} source $< (V_{SS} - 0.3)$).
- 6:** Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. If **Note 2**, $I_{ICL} = ((V_{SS} - 0.3) - V_{IL \text{ source}}) / R_S$. If **Note 3**, $I_{ICH} = (I_{CH \text{ source}} - (V_{DD} + 0.3)) / R_S$. R_S = Resistance between input source voltage and device pin. If $(V_{SS} - 0.3) \leq V_{SOURCE} \leq (V_{DD} + 0.3)$, injection current = 0.

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TABLE 30-10: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DO10	VOL	Output Low Voltage I/O Pins	—	—	0.4	V	IOL ≤ 10 mA, VDD = 3.3V
DO20	VOH	Output High Voltage I/O Pins	1.5 ⁽¹⁾	—	—	V	I _{OH} ≥ -14 mA, VDD = 3.3V
			2.0 ⁽¹⁾	—	—		I _{OH} ≥ -12 mA, VDD = 3.3V
			2.4	—	—		I _{OH} ≥ -10 mA, VDD = 3.3V
			3.0 ⁽¹⁾	—	—		I _{OH} ≥ -7 mA, VDD = 3.3V

Note 1: Parameters are characterized, but not tested.

TABLE 30-11: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	Symbol	Characteristics	Min. ⁽¹⁾	Typical	Max.	Units	Conditions
BO10	VBOR	BOR Event on VDD transition high-to-low ⁽²⁾	2.0	—	2.3	V	—

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

Note 2: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN.

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TABLE 30-12: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typical ⁽¹⁾	Max.	Units	Conditions
Program Flash Memory⁽³⁾							
D130	EP	Cell Endurance	20,000	—	—	E/W	—
D131	VPR	VDD for Read	2.3	—	3.6	V	—
D132	VPEW	VDD for Erase or Write	2.3	—	3.6	V	—
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	10	—	mA	—
	TWW	Word Write Cycle Time	—	411	—	FRC Cycles	See Note 4
D136	TRW	Row Write Cycle Time	—	6675	—		See Note 2,4
D137	TPE	Page Erase Cycle Time	—	20011	—		See Note 4
	TCE	Chip Erase Cycle Time	—	80180	—		See Note 4

- Note 1:** Data in “Typical” column is at 3.3V, 25°C unless otherwise stated.
- 2:** The minimum SYSCLK for row programming is 4 MHz. Care should be taken to minimize bus activities during row programming, such as suspending any memory-to-memory DMA operations. If heavy bus loads are expected, selecting Bus Matrix Arbitration mode 2 (rotating priority) may be necessary. The default Arbitration mode is mode 1 (CPU has lowest priority).
- 3:** Refer to the “PIC32 Flash Programming Specification” (DS60001145) for operating conditions during programming and erase cycles.
- 4:** This parameter depends on FRC accuracy (See [Table 30-19](#)) and FRC tuning values (See [Register 8-2](#)).

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30.2 AC Characteristics and Timing Parameters

The information contained in this section defines PIC32MX1XX/2XX 28/36/44-pin Family AC characteristics and timing parameters.

FIGURE 30-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

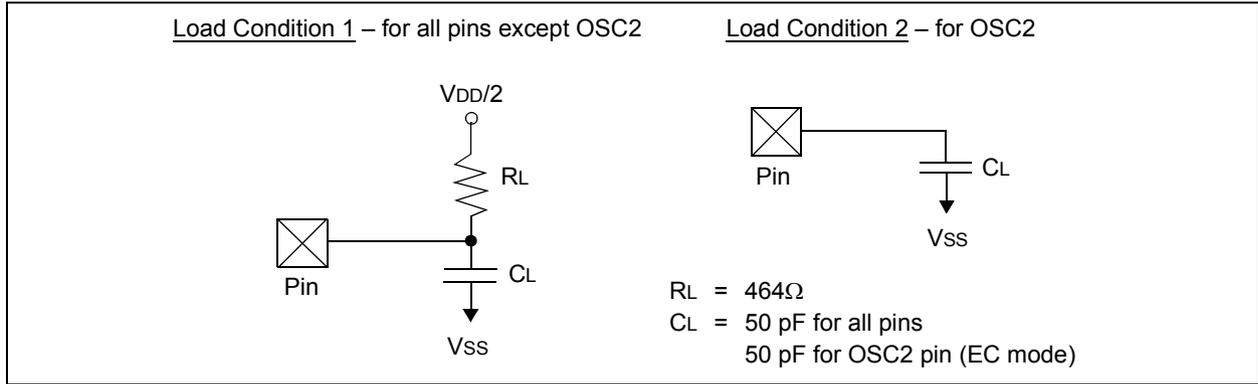
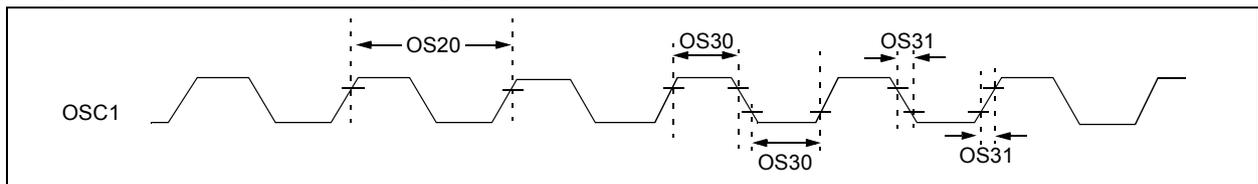


TABLE 30-16: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$ for Industrial $-40^\circ\text{C} \leq T_A \leq +105^\circ\text{C}$ for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typical ⁽¹⁾	Max.	Units	Conditions
DO56	C_{IO}	All I/O pins and OSC2	—	—	50	pF	EC mode
DO58	CB	SCLx, SDAx	—	—	400	pF	In I ² C mode

Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

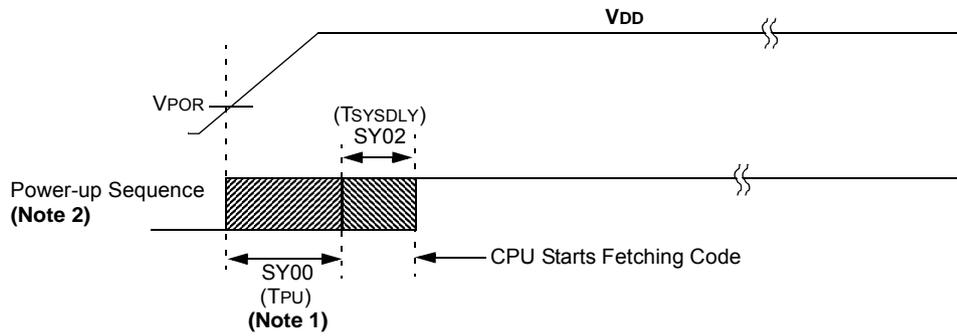
FIGURE 30-2: EXTERNAL CLOCK TIMING



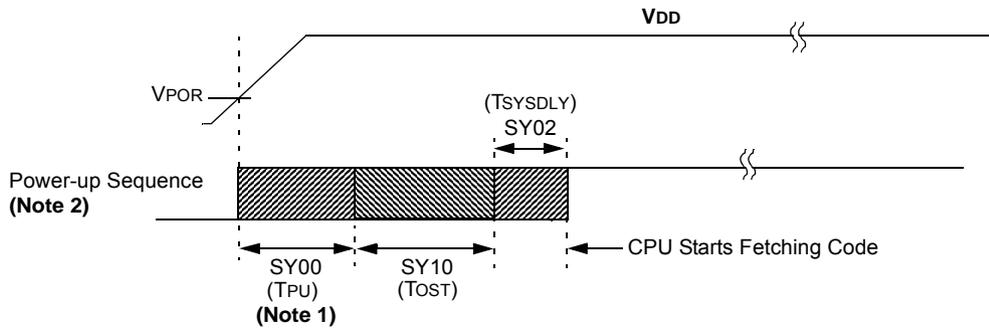
PIC32MX1XX/2XX 28/36/44-PIN FAMILY

FIGURE 30-4: POWER-ON RESET TIMING CHARACTERISTICS

Internal Voltage Regulator Enabled
Clock Sources = (FRC, FRCDIV, FRCDIV16, FRCPLL, EC, ECPLL and LPRC)



Internal Voltage Regulator Enabled
Clock Sources = (HS, HSPLL, XT, XTPLL and Sosc)



Note 1: The power-up period will be extended if the power-up sequence completes before the device exits from BOR ($V_{DD} < V_{DDMIN}$).

2: Includes interval voltage regulator stabilization delay.

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FIGURE 30-5: EXTERNAL RESET TIMING CHARACTERISTICS

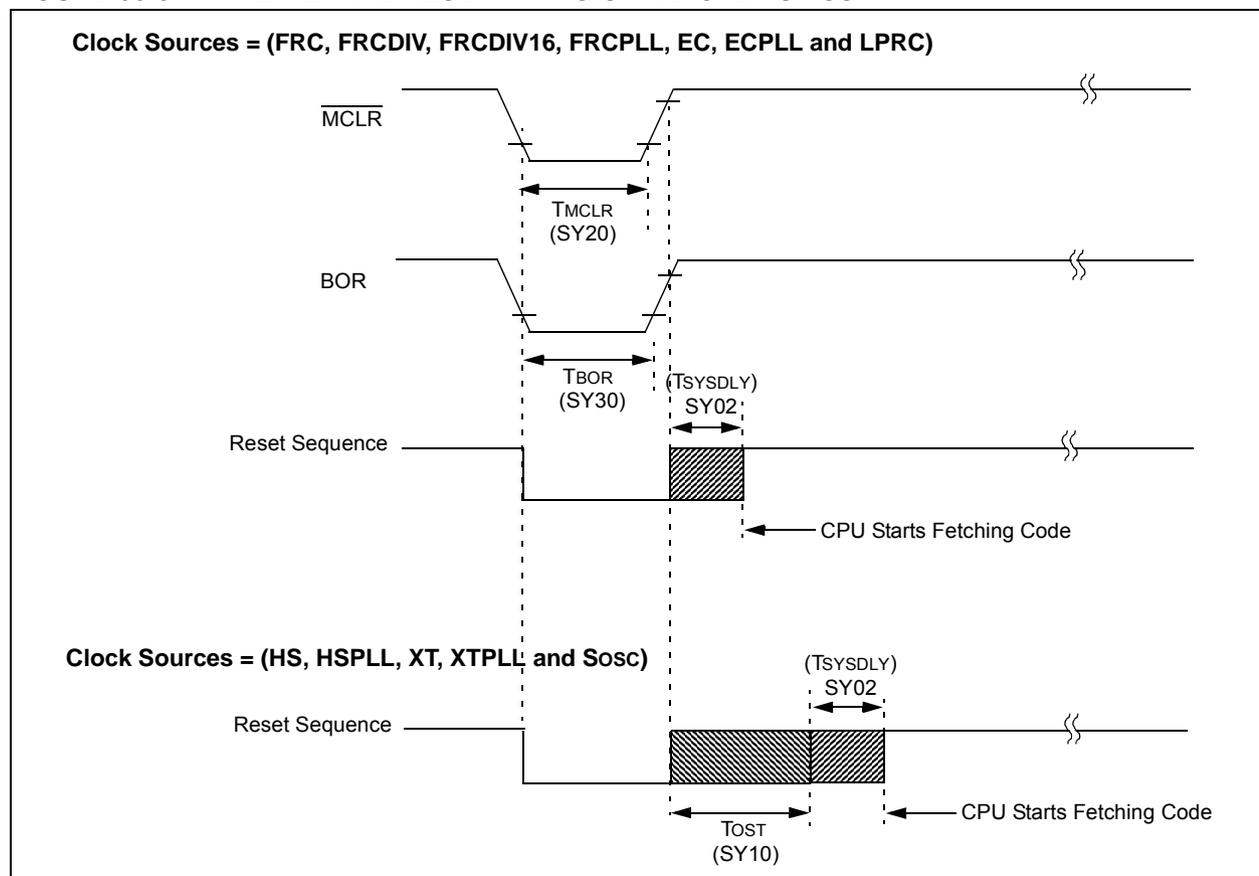


TABLE 30-22: RESETS TIMING

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical ⁽²⁾	Max.	Units	Conditions
SY00	TPU	Power-up Period Internal Voltage Regulator Enabled	—	400	600	µs	—
SY02	Tsysdly	System Delay Period: Time Required to Reload Device Configuration Fuses plus SYSCLK Delay before First instruction is Fetched.	—	1 µs + 8 SYSCLK cycles	—	—	—
SY20	TMCLR	MCLR Pulse Width (low)	2	—	—	µs	—
SY30	TBOR	BOR Pulse Width (low)	—	1	—	µs	—

- Note 1: These parameters are characterized, but not tested in manufacturing.
- Note 2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Characterized by design but not tested.

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TABLE 30-31: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS (CONTINUED)

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical ⁽²⁾	Max.	Units	Conditions
SP51	TssH2boZ	$\overline{\text{SS}}_x \uparrow$ to SDOx Output High-Impedance (Note 4)	5	—	25	ns	—
SP52	Tsch2ssH TscL2ssH	$\overline{\text{SS}}_x \uparrow$ after SCKx Edge	TsCK + 20	—	—	ns	—
SP60	TssL2boV	SDOx Data Output Valid after $\overline{\text{SS}}_x$ Edge	—	—	25	ns	—

- Note 1:** These parameters are characterized, but not tested in manufacturing.
- 2:** Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.
- 3:** The minimum clock period for SCKx is 50 ns.
- 4:** Assumes 50 pF load on all SPIx pins.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

FIGURE 30-14: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)

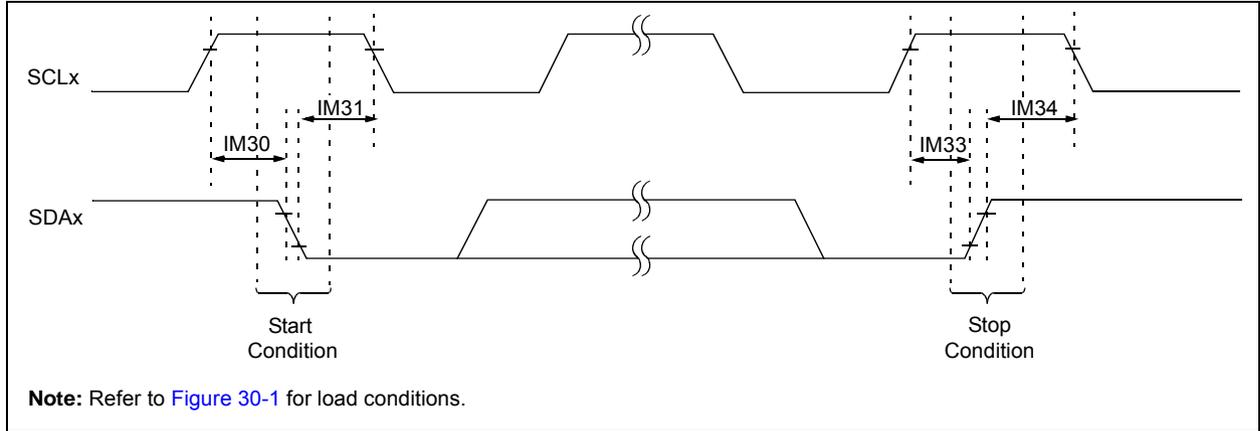
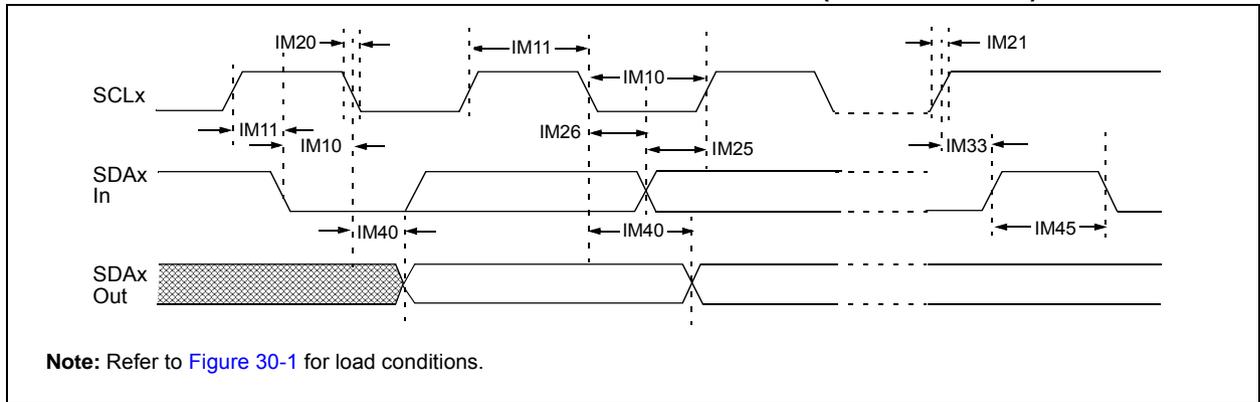


FIGURE 30-15: I2Cx BUS DATA TIMING CHARACTERISTICS (MASTER MODE)



PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-32: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE) (CONTINUED)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp			
Param. No.	Symbol	Characteristics		Min. ⁽¹⁾	Max.	Units	Conditions
IM40	TAA:SCL	Output Valid from Clock	100 kHz mode	—	3500	ns	—
			400 kHz mode	—	1000	ns	—
			1 MHz mode (Note 2)	—	350	ns	—
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	μs	The amount of time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
			1 MHz mode (Note 2)	0.5	—	μs	
IM50	CB	Bus Capacitive Loading		—	400	pF	—
IM51	TPGD	Pulse Gobbler Delay		52	312	ns	See Note 3

Note 1: BRG is the value of the I²C Baud Rate Generator.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: The typical value for this parameter is 104 ns.

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FIGURE 30-16: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (SLAVE MODE)

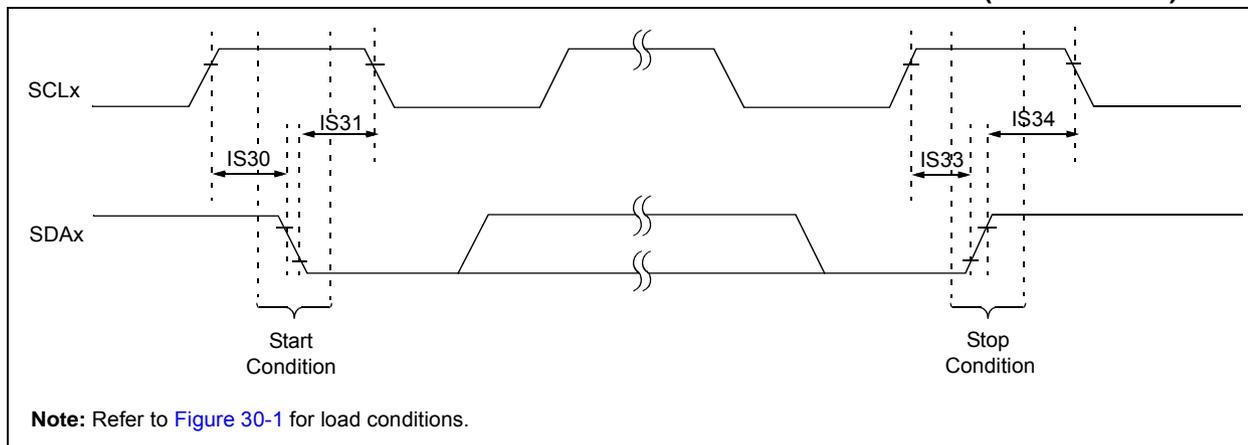
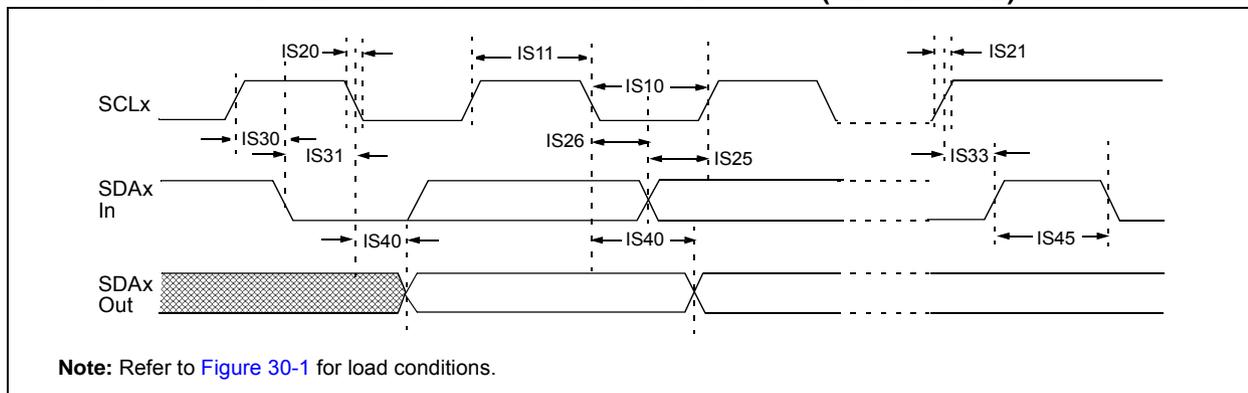


FIGURE 30-17: I2Cx BUS DATA TIMING CHARACTERISTICS (SLAVE MODE)



PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-33: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE) (CONTINUED)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	Symbol	Characteristics		Min.	Max.	Units	Conditions
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	ns	—
			400 kHz mode	600	—	ns	
			1 MHz mode (Note 1)	250		ns	
IS40	TAA:SCL	Output Valid from Clock	100 kHz mode	0	3500	ns	—
			400 kHz mode	0	1000	ns	
			1 MHz mode (Note 1)	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	μs	The amount of time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
			1 MHz mode (Note 1)	0.5	—	μs	
IS50	CB	Bus Capacitive Loading		—	400	pF	—

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

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TABLE 30-34: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions (see Note 5): 2.5V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typical	Max.	Units	Conditions
ADC Accuracy – Measurements with Internal VREF+/VREF-							
AD20d	Nr	Resolution	10 data bits			bits	(Note 3)
AD21d	INL	Integral Non-linearity	> -1	—	< 1	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V (Note 3)
AD22d	DNL	Differential Non-linearity	> -1	—	< 1	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V (Notes 2,3)
AD23d	GERR	Gain Error	> -4	—	< 4	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V (Note 3)
AD24d	E _{OFF}	Offset Error	> -2	—	< 2	Lsb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V (Note 3)
AD25d	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance							
AD32b	SINAD	Signal to Noise and Distortion	55	58.5	—	dB	(Notes 3,4)
AD34b	ENOB	Effective Number of bits	9.0	9.5	—	bits	(Notes 3,4)

- Note 1:** These parameters are not characterized or tested in manufacturing.
- 2:** With no missing codes.
- 3:** These parameters are characterized, but not tested in manufacturing.
- 4:** Characterized with a 1 kHz sine wave.
- 5:** The ADC module is functional at $V_{BORMIN} < V_{DD} < 2.5V$, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-35: 10-BIT CONVERSION RATE PARAMETERS

AC CHARACTERISTICS ⁽²⁾			Standard Operating Conditions (see Note 3): 2.5V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp		
ADC Speed	TAD Min.	Sampling Time Min.	Rs Max.	VDD	ADC Channels Configuration
1 Msps to 400 ksps ⁽¹⁾	65 ns	132 ns	500Ω	3.0V to 3.6V	
Up to 400 ksps	200 ns	200 ns	5.0 kΩ	2.5V to 3.6V	

- Note 1:** External VREF- and VREF+ pins must be used for correct operation.
- 2:** These parameters are characterized, but not tested in manufacturing.
- 3:** The ADC module is functional at $V_{BORMIN} < V_{DD} < 2.5\text{V}$, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

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TABLE 30-36: ANALOG-TO-DIGITAL CONVERSION TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions (see Note 4): 2.5V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typical ⁽¹⁾	Max.	Units	Conditions
Clock Parameters							
AD50	TAD	ADC Clock Period ⁽²⁾	65	—	—	ns	See Table 30-35
Conversion Rate							
AD55	TCONV	Conversion Time	—	12 TAD	—	—	—
AD56	FCNV	Throughput Rate (Sampling Speed)	—	—	1000	ksps	AVDD = 3.0V to 3.6V
			—	—	400	ksps	AVDD = 2.5V to 3.6V
AD57	TSAMP	Sample Time	1 TAD	—	—	—	TSAMP must be ≥ 132 ns
Timing Parameters							
AD60	TPCS	Conversion Start from Sample Trigger ⁽³⁾	—	1.0 TAD	—	—	Auto-Convert Trigger (SSRC<2:0> = 111) not selected
AD61	TPSS	Sample Start from Setting Sample (SAMP) bit	0.5 TAD	—	1.5 TAD	—	—
AD62	TCSS	Conversion Completion to Sample Start (ASAM = 1) ⁽³⁾	—	0.5 TAD	—	—	—
AD63	TDFPU	Time to Stabilize Analog Stage from ADC Off to ADC On ⁽³⁾	—	—	2	μs	—

Note 1: These parameters are characterized, but not tested in manufacturing.

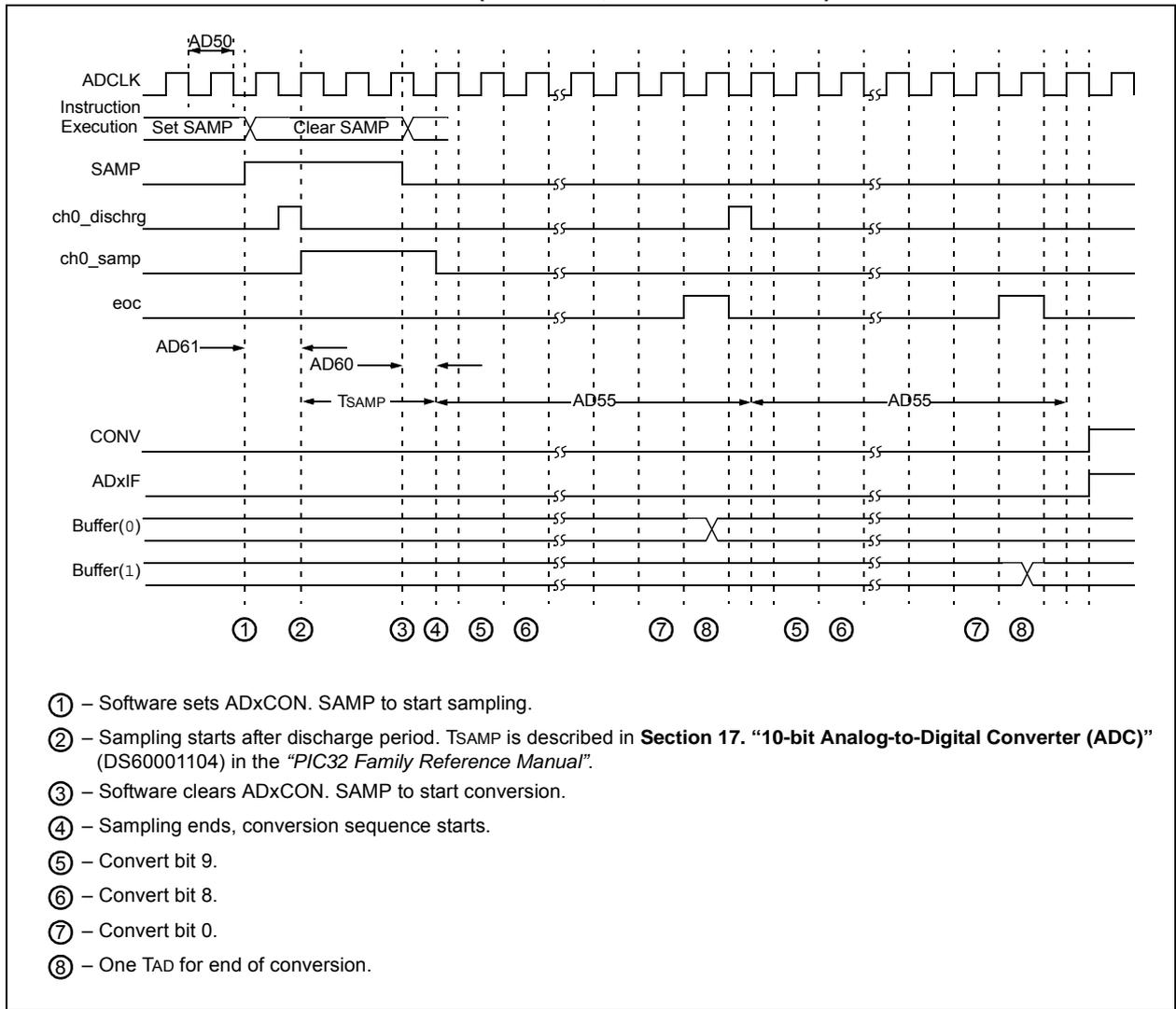
2: Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.

3: Characterized by design but not tested.

4: The ADC module is functional at $V_{BORMIN} < V_{DD} < 2.5\text{V}$, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

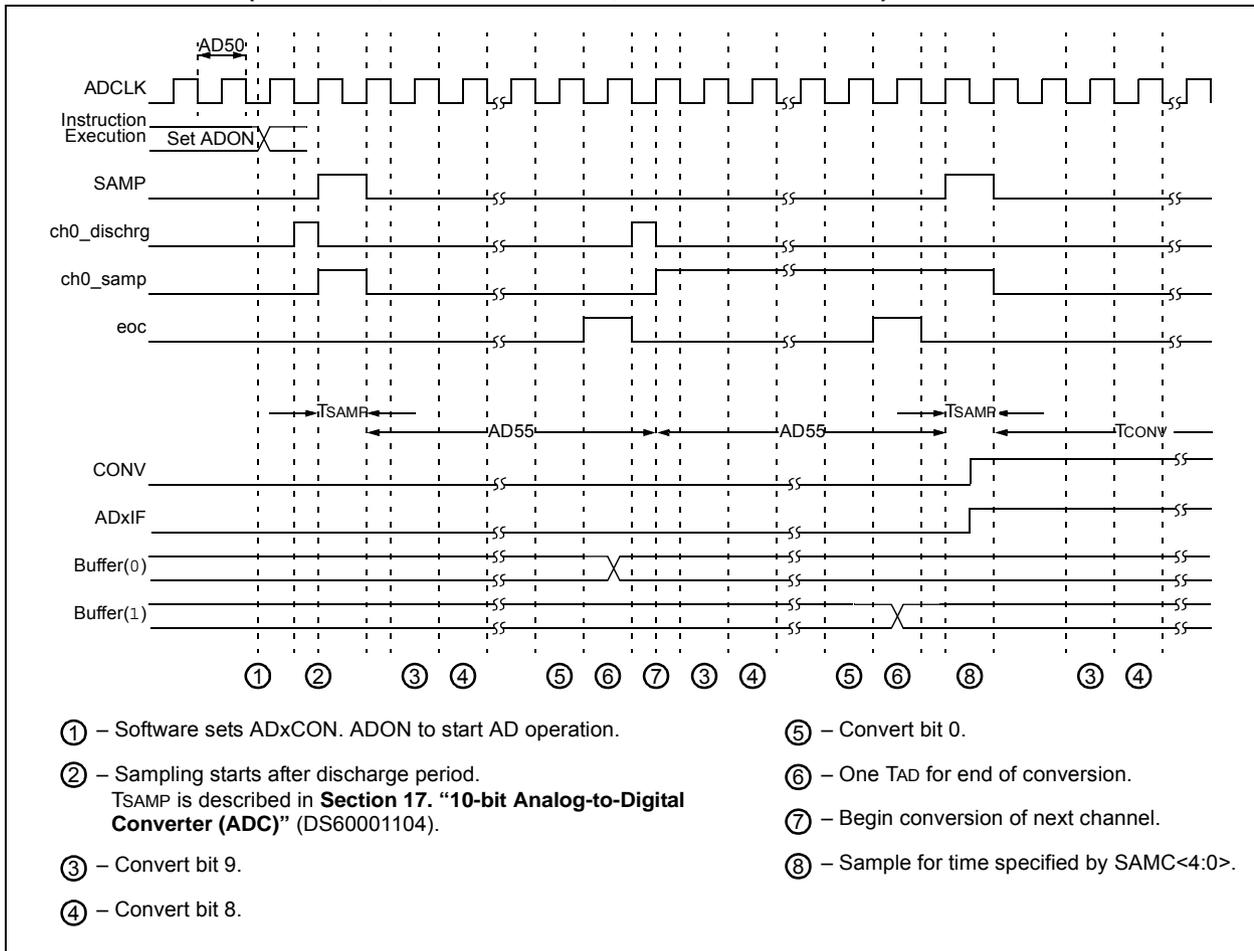
FIGURE 30-18: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 0, SSRC<2:0> = 000)



- ① – Software sets ADxCON. SAMP to start sampling.
- ② – Sampling starts after discharge period. T_{SAMP} is described in **Section 17. “10-bit Analog-to-Digital Converter (ADC)”** (DS60001104) in the “PIC32 Family Reference Manual”.
- ③ – Software clears ADxCON. SAMP to start conversion.
- ④ – Sampling ends, conversion sequence starts.
- ⑤ – Convert bit 9.
- ⑥ – Convert bit 8.
- ⑦ – Convert bit 0.
- ⑧ – One TAD for end of conversion.

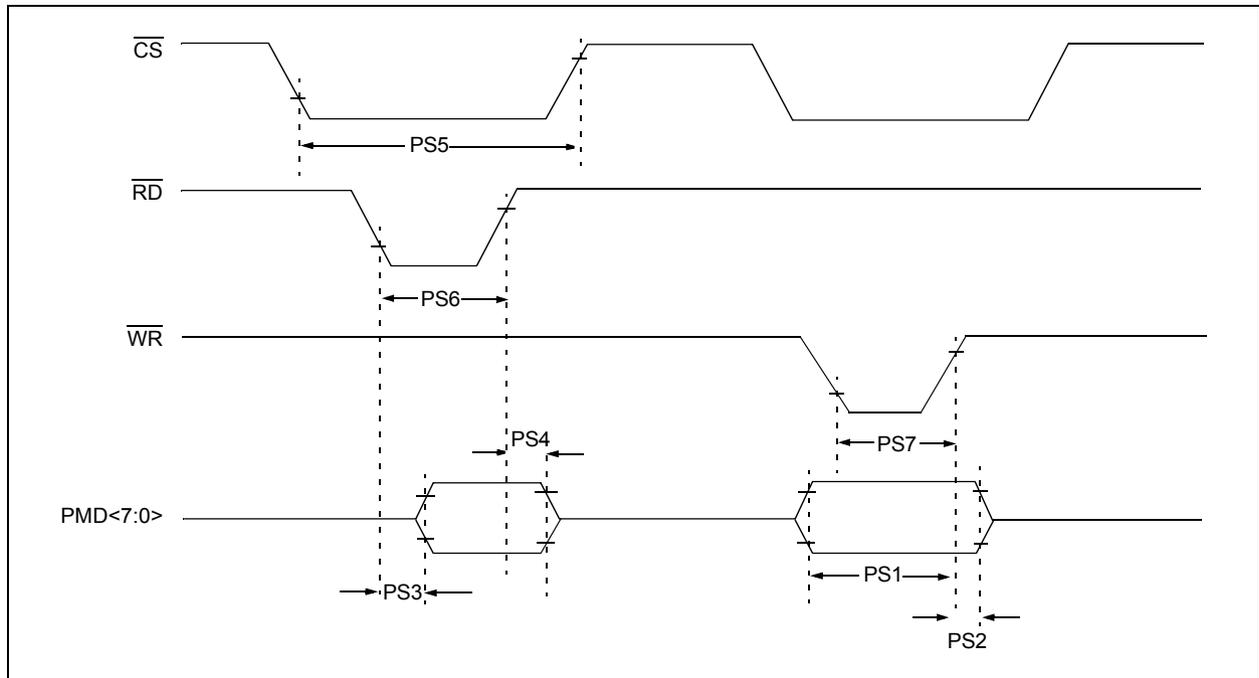
PIC32MX1XX/2XX 28/36/44-PIN FAMILY

FIGURE 30-19: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



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FIGURE 30-20: PARALLEL SLAVE PORT TIMING



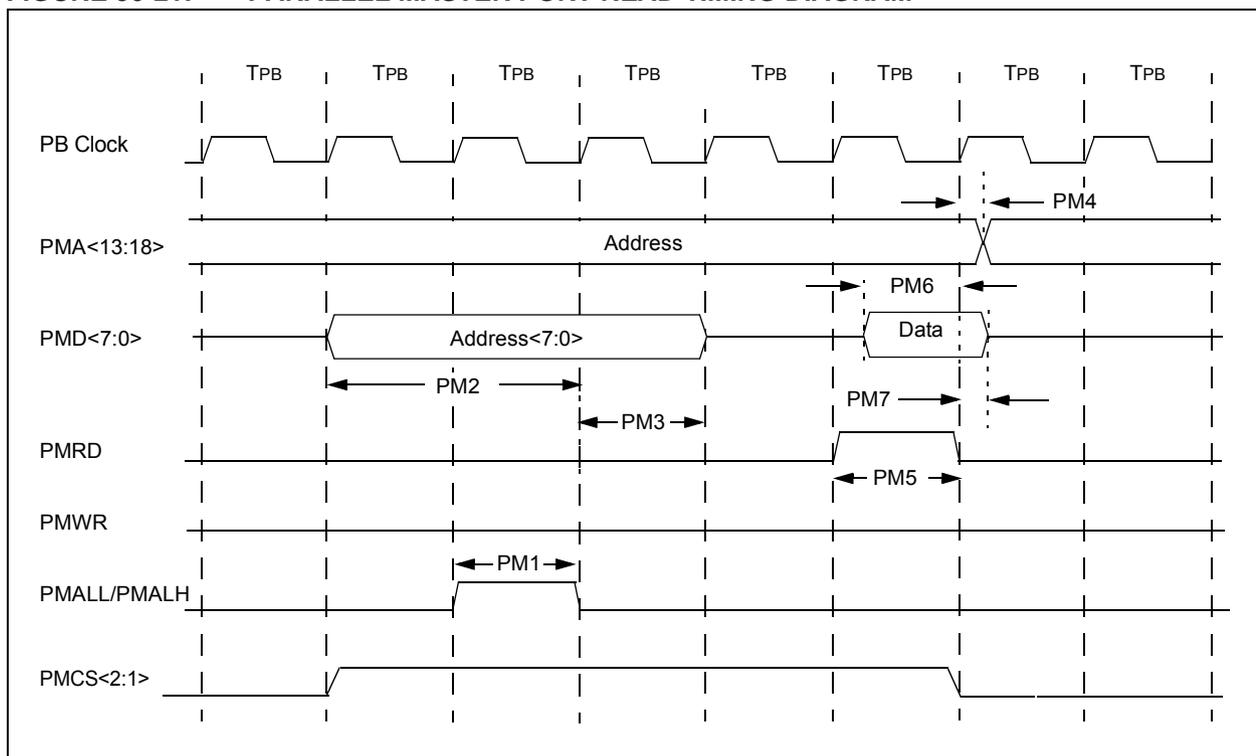
PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-37: PARALLEL SLAVE PORT REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp				
Para m.No.	Symbol	Characteristics ⁽¹⁾	Min.	Typ.	Max.	Units	Conditions
PS1	TdtV2wr H	Data In Valid before $\overline{\text{WR}}$ or $\overline{\text{CS}}$ Inactive (setup time)	20	—	—	ns	—
PS2	TwrH2dt l	$\overline{\text{WR}}$ or $\overline{\text{CS}}$ Inactive to Data-In Invalid (hold time)	40	—	—	ns	—
PS3	TrdL2dt V	$\overline{\text{RD}}$ and $\overline{\text{CS}}$ Active to Data-Out Valid	—	—	60	ns	—
PS4	TrdH2dtl	$\overline{\text{RD}}$ Active or $\overline{\text{CS}}$ Inactive to Data-Out Invalid	0	—	10	ns	—
PS5	Tcs	$\overline{\text{CS}}$ Active Time	TPB + 40	—	—	ns	—
PS6	TWR	$\overline{\text{WR}}$ Active Time	TPB + 25	—	—	ns	—
PS7	TRD	$\overline{\text{RD}}$ Active Time	TPB + 25	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 30-21: PARALLEL MASTER PORT READ TIMING DIAGRAM



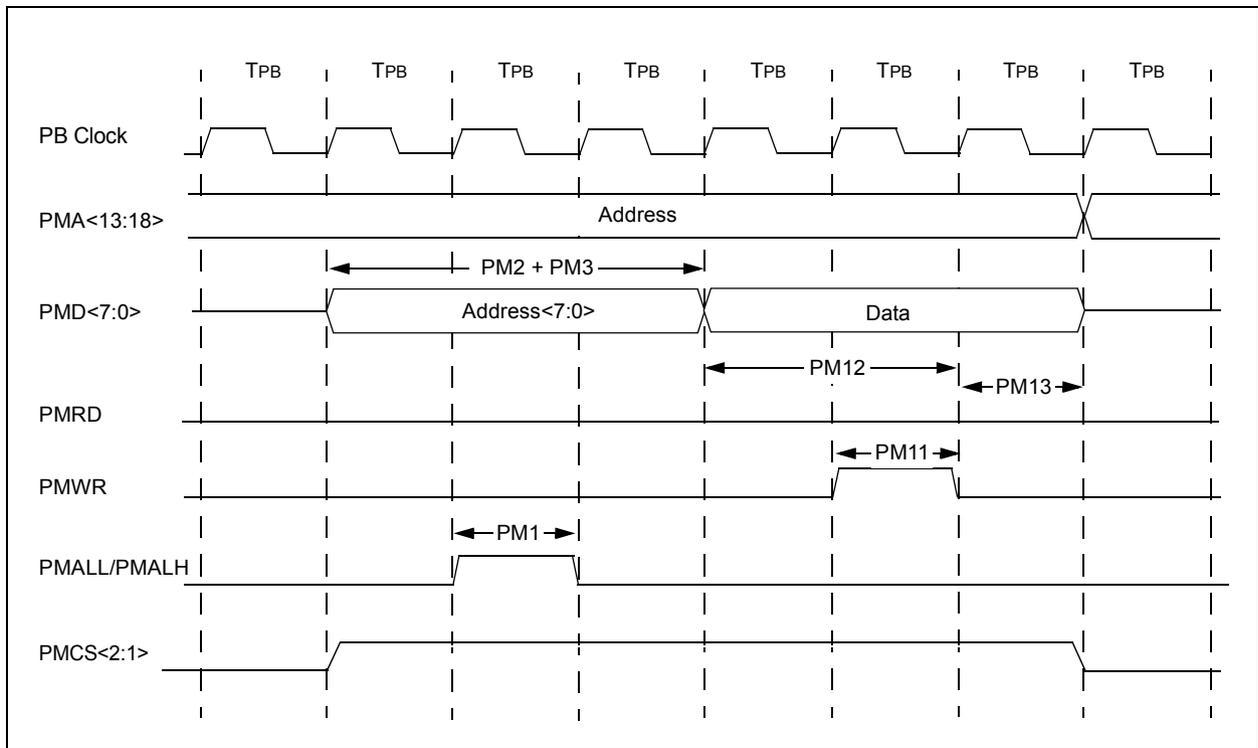
PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-38: PARALLEL MASTER PORT READ TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)				
			Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typ.	Max.	Units	Conditions
PM1	TLAT	PMALL/PMALH Pulse Width	—	1 TPB	—	—	—
PM2	TADSU	Address Out Valid to PMALL/PMALH Invalid (address setup time)	—	2 TPB	—	—	—
PM3	TADHOLD	PMALL/PMALH Invalid to Address Out Invalid (address hold time)	—	1 TPB	—	—	—
PM4	TAHOLD	PMRD Inactive to Address Out Invalid (address hold time)	5	—	—	ns	—
PM5	TRD	PMRD Pulse Width	—	1 TPB	—	—	—
PM6	TDSU	PMRD or PMENB Active to Data In Valid (data setup time)	15	—	—	ns	—
PM7	TDHOLD	PMRD or PMENB Inactive to Data In Invalid (data hold time)	—	80	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 30-22: PARALLEL MASTER PORT WRITE TIMING DIAGRAM



PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-39: PARALLEL MASTER PORT WRITE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typ.	Max.	Units	Conditions
PM11	TWR	PMWR Pulse Width	—	1 TPB	—	—	—
PM12	TDVSSU	Data Out Valid before PMWR or PMENB goes Inactive (data setup time)	—	2 TPB	—	—	—
PM13	TDVHOLD	PMWR or PMEMB Invalid to Data Out Invalid (data hold time)	—	1 TPB	—	—	—

Note 1: These parameters are characterized, but not tested in manufacturing.

TABLE 30-40: OTG ELECTRICAL SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typ.	Max.	Units	Conditions
USB313	VUSB3V3	USB Voltage	3.0	—	3.6	V	Voltage on VUSB3V3 must be in this range for proper USB operation
USB315	VILUSB	Input Low Voltage for USB Buffer	—	—	0.8	V	—
USB316	VIHUSB	Input High Voltage for USB Buffer	2.0	—	—	V	—
USB318	VDIFS	Differential Input Sensitivity	—	—	0.2	V	The difference between D+ and D- must exceed this value while VCM is met
USB319	VCM	Differential Common Mode Range	0.8	—	2.5	V	—
USB320	ZOUT	Driver Output Impedance	28.0	—	44.0	Ω	—
USB321	Vol	Voltage Output Low	0.0	—	0.3	V	1.425 k Ω load connected to VUSB3V3
USB322	VoH	Voltage Output High	2.8	—	3.6	V	1.425 k Ω load connected to ground

Note 1: These parameters are characterized, but not tested in manufacturing.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-41: CTMU CURRENT SOURCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 3):2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
CTMU CURRENT SOURCE							
CTMUI1	IOUT1	Base Range ⁽¹⁾	—	0.55	—	μA	CTMUCON<9:8> = 01
CTMUI2	IOUT2	10x Range ⁽¹⁾	—	5.5	—	μA	CTMUCON<9:8> = 10
CTMUI3	IOUT3	100x Range ⁽¹⁾	—	55	—	μA	CTMUCON<9:8> = 11
CTMUI4	IOUT4	1000x Range ⁽¹⁾	—	550	—	μA	CTMUCON<9:8> = 00
CTMUFV1	VF	Temperature Diode Forward Voltage ^(1,2)	—	0.598	—	V	$T_A = +25^{\circ}\text{C}$, CTMUCON<9:8> = 01
			—	0.658	—	V	$T_A = +25^{\circ}\text{C}$, CTMUCON<9:8> = 10
			—	0.721	—	V	$T_A = +25^{\circ}\text{C}$, CTMUCON<9:8> = 11
CTMUFV2	VFVR	Temperature Diode Rate of Change ^(1,2)	—	-1.92	—	$\text{mV}/^{\circ}\text{C}$	CTMUCON<9:8> = 01
			—	-1.74	—	$\text{mV}/^{\circ}\text{C}$	CTMUCON<9:8> = 10
			—	-1.56	—	$\text{mV}/^{\circ}\text{C}$	CTMUCON<9:8> = 11

Note 1: Nominal value at center point of current trim range (CTMUCON<15:10> = 000000).

2: Parameters are characterized but not tested in manufacturing. Measurements taken with the following conditions:

- VREF+ = AVDD = 3.3V
- ADC module configured for conversion speed of 500 ksp/s
- All PMD bits are cleared (PMDx = 0)
- Executing a `while(1)` statement
- Device operating from the FRC with no PLL

3: The CTMU module is functional at $V_{BORMIN} < V_{DD} < V_{DDMIN}$, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

FIGURE 30-23: EJTAG TIMING CHARACTERISTICS

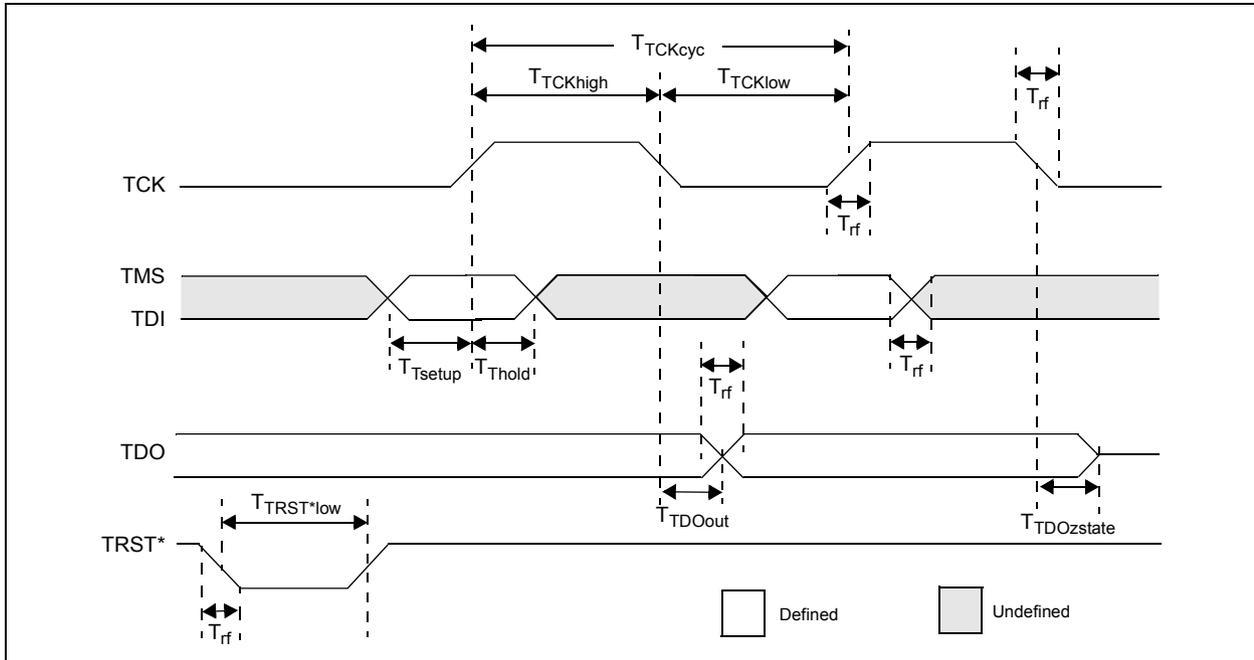


TABLE 30-42: EJTAG TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp			
Param. No.	Symbol	Description ⁽¹⁾	Min.	Max.	Units	Conditions
EJ1	TTCKCYC	TCK Cycle Time	25	—	ns	—
EJ2	TTCKHIGH	TCK High Time	10	—	ns	—
EJ3	TTCKLOW	TCK Low Time	10	—	ns	—
EJ4	TTSETUP	TAP Signals Setup Time Before Rising TCK	5	—	ns	—
EJ5	TTHOLD	TAP Signals Hold Time After Rising TCK	3	—	ns	—
EJ6	TTDOOUT	TDO Output Delay Time from Falling TCK	—	5	ns	—
EJ7	TTDOZSTATE	TDO 3-State Delay Time from Falling TCK	—	5	ns	—
EJ8	TTRSTLOW	TRST Low Time	25	—	ns	—
EJ9	TRF	TAP Signals Rise/Fall Time, All Input and Output	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

31.0 50 MHz ELECTRICAL CHARACTERISTICS

This section provides an overview of the PIC32MX1XX/2XX 28/36/44-pin Family electrical characteristics for devices operating at 50 MHz.

The specifications for 50 MHz are identical to those shown in [Section 30.0 “Electrical Characteristics”](#), with the exception of the parameters listed in this chapter.

Parameters in this chapter begin with the letter “M”, which denotes 50 MHz operation. For example, parameter DC29a in [Section 30.0 “Electrical Characteristics”](#), is the up to 40 MHz operation equivalent for MDC29a.

Absolute maximum ratings for the PIC32MX1XX/2XX 28/36/44-pin Family 50 MHz devices are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions, above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings

(See Note 1)

Ambient temperature under bias	-40°C to +85°C
Storage temperature	-65°C to +150°C
Voltage on VDD with respect to VSS	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to VSS (Note 3).....	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 2.3V (Note 3).....	-0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to VSS when VDD < 2.3V (Note 3).....	-0.3V to +3.6V
Voltage on D+ or D- pin with respect to VUSB3V3	-0.3V to (VUSB3V3 + 0.3V)
Voltage on VBUS with respect to VSS	-0.3V to +5.5V
Maximum current out of VSS pin(s)	300 mA
Maximum current into VDD pin(s) (Note 2).....	300 mA
Maximum output current sunk by any I/O pin.....	15 mA
Maximum output current sourced by any I/O pin	15 mA
Maximum current sunk by all ports	200 mA
Maximum current sourced by all ports (Note 2).....	200 mA

Note 1: Stresses above those listed under “**Absolute Maximum Ratings**” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions, above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see [Table 30-2](#)).

3: See the “[Pin Diagrams](#)” section for the 5V tolerant pins.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

31.1 DC Characteristics

TABLE 31-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts) ⁽¹⁾	Temp. Range (in °C)	Max. Frequency
			PIC32MX1XX/2XX 28/36/44-pin Family
MDC5	2.3-3.6V	-40°C to +85°C	50 MHz

Note 1: Overall functional device operation at $V_{BORMIN} < V_{DD} < V_{DDMIN}$ is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below V_{DDMIN} . Refer to parameter BO10 in [Table 30-11](#) for BOR values.

TABLE 31-2: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial		
Parameter No.	Typical ⁽³⁾	Max.	Units	Conditions	
Operating Current (IDD) (Note 1, 2)					
MDC24	25	37	mA	50 MHz	

Note 1: A device's I_{DD} supply current is mainly a function of the operating voltage and frequency. Other factors, such as PBCLK (Peripheral Bus Clock) frequency, number of peripheral modules enabled, internal code execution pattern, execution from Program Flash memory vs. SRAM, I/O pin loading and switching rate, oscillator type, as well as temperature, can have an impact on the current consumption.

2: The test conditions for I_{DD} measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU, Program Flash, and SRAM data memory are operational, SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is cleared
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{\text{MCLR}} = V_{DD}$
- CPU executing `while(1)` statement from Flash

3: RTCC and JTAG are disabled

4: Data in "Typical" column is at 3.3V, 25°C at specified operating frequency unless otherwise stated. Parameters are for design guidance only and are not tested.

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TABLE 31-3: DC CHARACTERISTICS: IDLE CURRENT (I_{IDLE})

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial	
Parameter No.	Typical ⁽²⁾	Max.	Units	Conditions
Idle Current (I_{IDLE}): Core Off, Clock on Base Current (Note 1)				
MDC34a	8	13	mA	50 MHz

Note 1: The test conditions for I_{IDLE} current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Idle mode (CPU core Halted), and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is cleared
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{\text{MCLR}} = V_{DD}$
- RTCC and JTAG are disabled

2: Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 31-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial	
Param. No.	Typical ⁽²⁾	Max.	Units	Conditions
Power-Down Current (I_{PD}) (Note 1)				
MDC40k	10	25	μA	-40°C +85°C Base Power-Down Current
MDC40n	250	500	μA	
Module Differential Current				
MDC41e	10	55	μA	3.6V Watchdog Timer Current: ΔI_{WDT} (Note 3)
MDC42e	23	55	μA	3.6V RTCC + Timer1 w/32 kHz Crystal: ΔI_{RTCC} (Note 3)
MDC43d	1100	1300	μA	3.6V ADC: ΔI_{ADC} (Notes 3,4)

Note 1: The test conditions for I_{PD} current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is set
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{\text{MCLR}} = V_{DD}$
- RTCC and JTAG are disabled

2: Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

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TABLE 31-5: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial				
Param. No.	Symbol	Characteristics	Min.	Typical	Max.	Units	Conditions
MOS10	Fosc	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC 4	— —	50 50	MHz MHz	EC (Note 2) ECPLL (Note 1)

Note 1: PLL input requirements: $4\text{ MHz} \leq F_{\text{PLLIN}} \leq 5\text{ MHz}$ (use PLL prescaler to reduce Fosc). This parameter is characterized, but tested at 10 MHz only at manufacturing.

2: This parameter is characterized, but not tested in manufacturing.

TABLE 31-6: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial				
Param. No.	Symbol	Characteristics	Min.	Typical	Max.	Units	Conditions
MSP10	TscL	SCKx Output Low Time (Note 1,2)	Tsck/2	—	—	ns	—
MSP11	Tsch	SCKx Output High Time (Note 1,2)	Tsck/2	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

TABLE 31-7: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typ.	Max.	Units	Conditions
MSP10	TscL	SCKx Output Low Time (Note 1,2)	Tsck/2	—	—	ns	—
MSP11	Tsch	SCKx Output High Time (Note 1,2)	Tsck/2	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 31-8: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typ.	Max.	Units	Conditions
MSP70	TsCL	SCKx Input Low Time (Note 1,2)	TsCK/2	—	—	ns	—
MSP71	TsCH	SCKx Input High Time (Note 1,2)	TsCK/2	—	—	ns	—
MSP51	TssH2bOZ	$\overline{\text{SS}}_x \uparrow$ to SDOx Output High-Impedance (Note 2)	5	—	25	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: The minimum clock period for SCKx is 40 ns.

TABLE 31-9: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial				
Param. No.	Symbol	Characteristics	Min.	Typical	Max.	Units	Conditions
SP70	TsCL	SCKx Input Low Time (Note 1,2)	TsCK/2	—	—	ns	—
SP71	TsCH	SCKx Input High Time (Note 1,2)	TsCK/2	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: The minimum clock period for SCKx is 40 ns.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

NOTES:

32.0 DC AND AC DEVICE CHARACTERISTICS GRAPHS

Note: The graphs provided following this note are a statistical summary based on a limited number of samples and are provided for design guidance purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

FIGURE 32-1: I/O OUTPUT VOLTAGE HIGH (VOH)

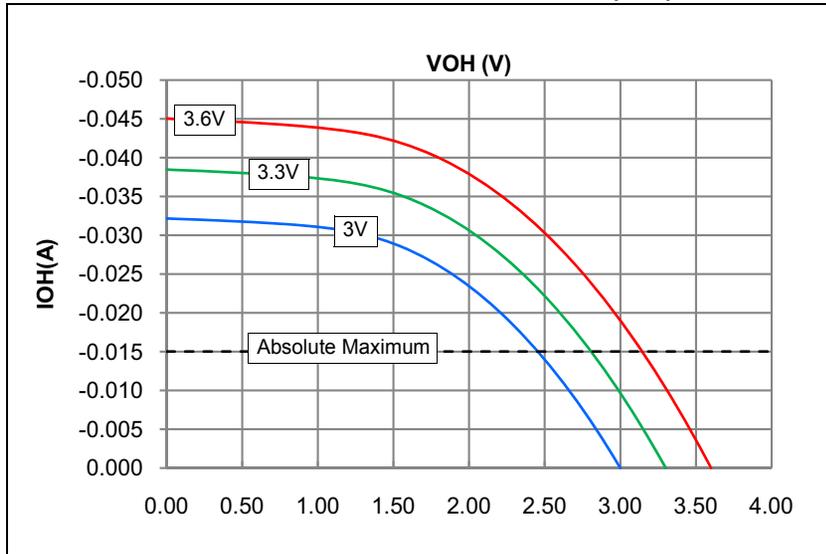


FIGURE 32-2: I/O OUTPUT VOLTAGE LOW (VOL)

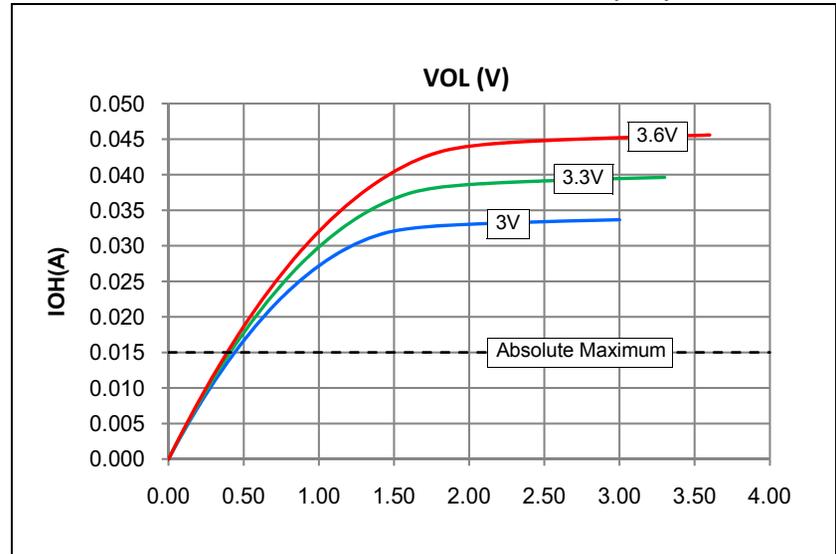


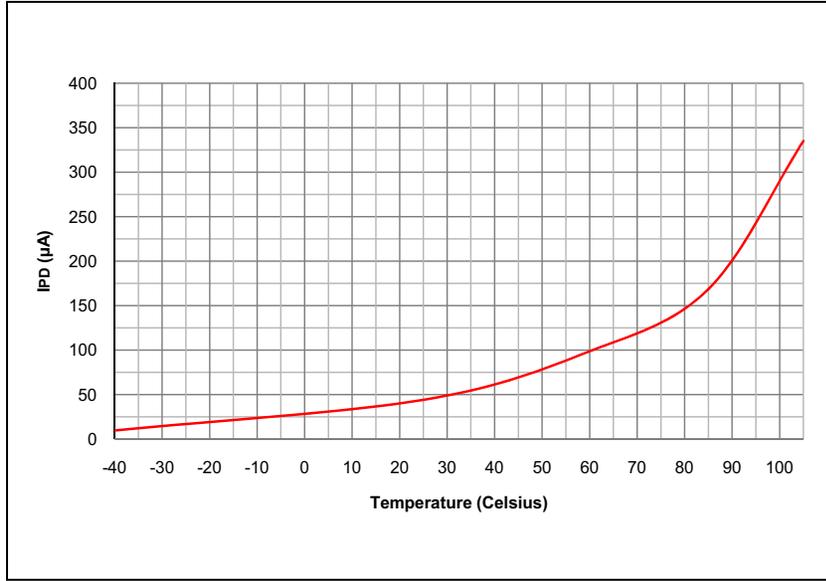
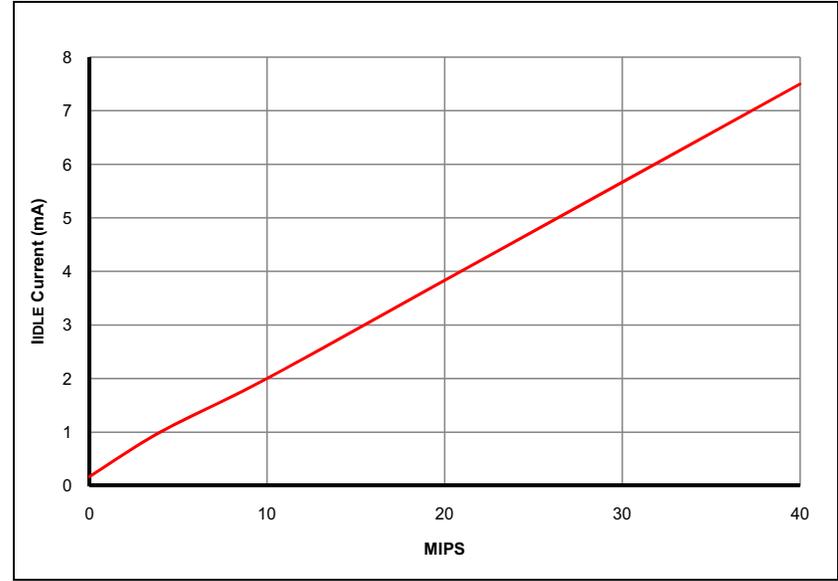
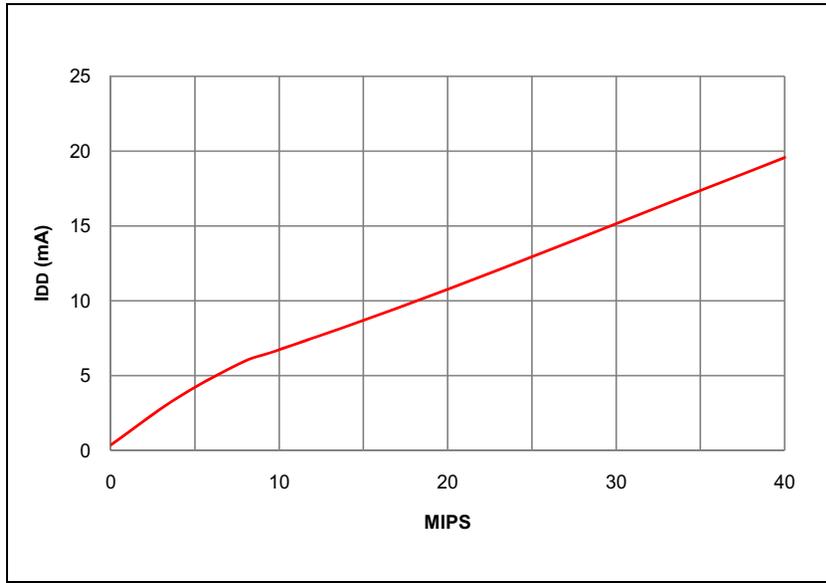
FIGURE 32-3: TYPICAL I_{PD} CURRENT @ $V_{DD} = 3.3V$ **FIGURE 32-5: TYPICAL I_{IDLE} CURRENT @ $V_{DD} = 3.3V$** **FIGURE 32-4: TYPICAL I_{DD} CURRENT @ $V_{DD} = 3.3V$** 

FIGURE 32-6: TYPICAL FRC FREQUENCY @ VDD = 3.3V

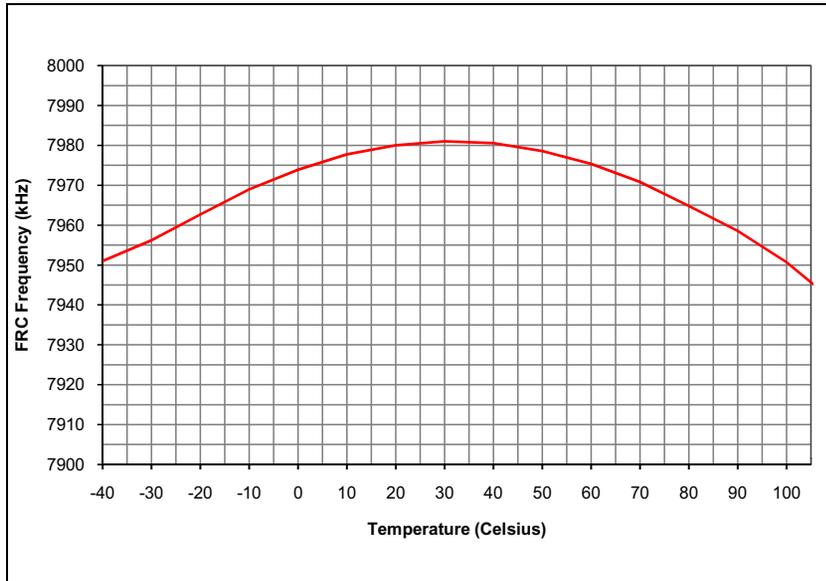


FIGURE 32-7: TYPICAL LPRC FREQUENCY @ VDD = 3.3V

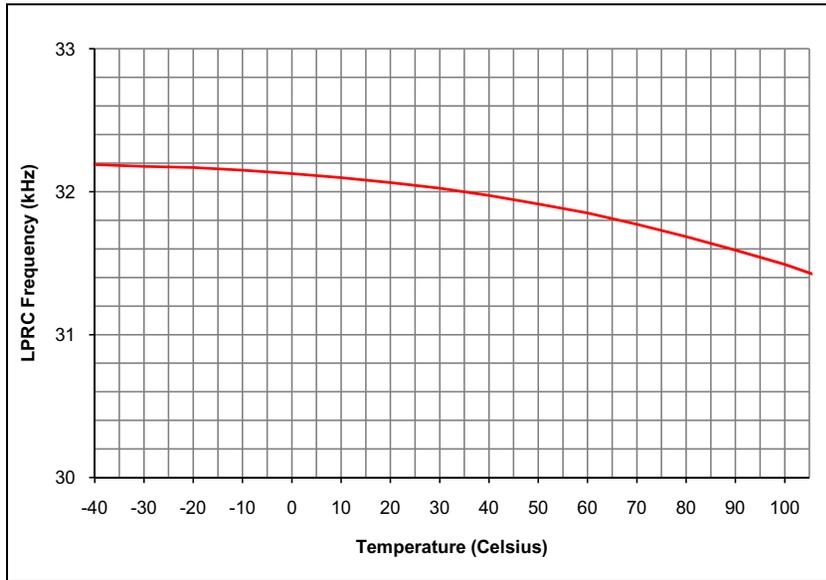
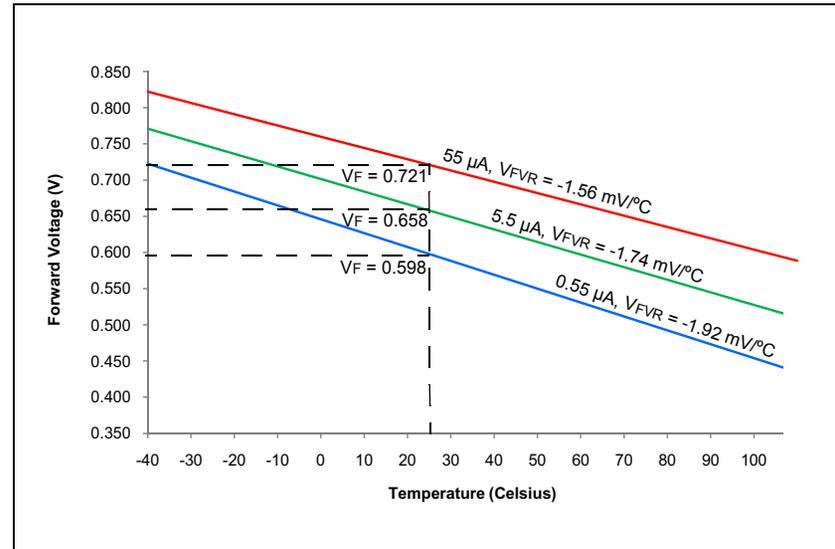


FIGURE 32-8: TYPICAL CTMU TEMPERATURE DIODE FORWARD VOLTAGE



PIC32MX1XX/2XX 28/36/44-PIN FAMILY

NOTES:

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

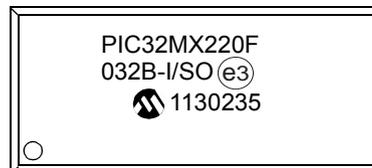
33.0 PACKAGING INFORMATION

33.1 Package Marking Information

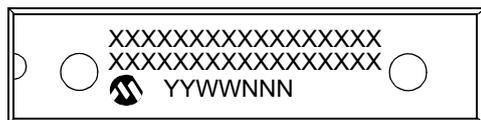
28-Lead SOIC



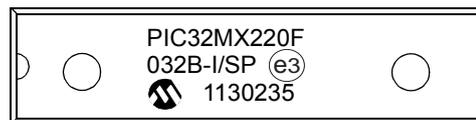
Example



28-Lead SPDIP



Example



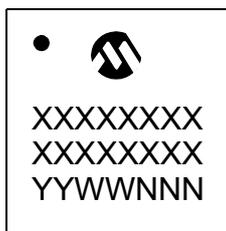
28-Lead SSOP



Example



28-Lead QFN



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
Note: If the full Microchip part number cannot be marked on one line, it is carried over to the next line, thus limiting the number of available characters for customer-specific information.		

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

33.1 Package Marking Information (Continued)

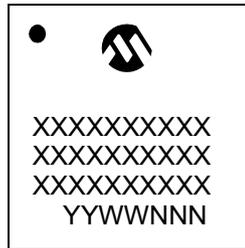
36-Lead VTLA



Example



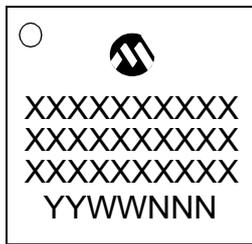
44-Lead VTLA



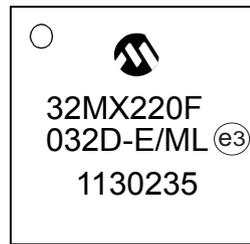
Example



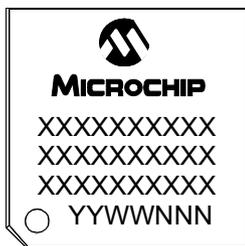
44-Lead QFN



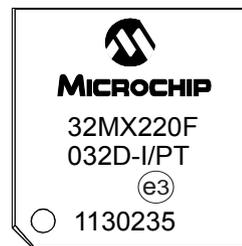
Example



44-Lead TQFP



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	* (e3)	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: If the full Microchip part number cannot be marked on one line, it is carried over to the next line, thus limiting the number of available characters for customer-specific information.

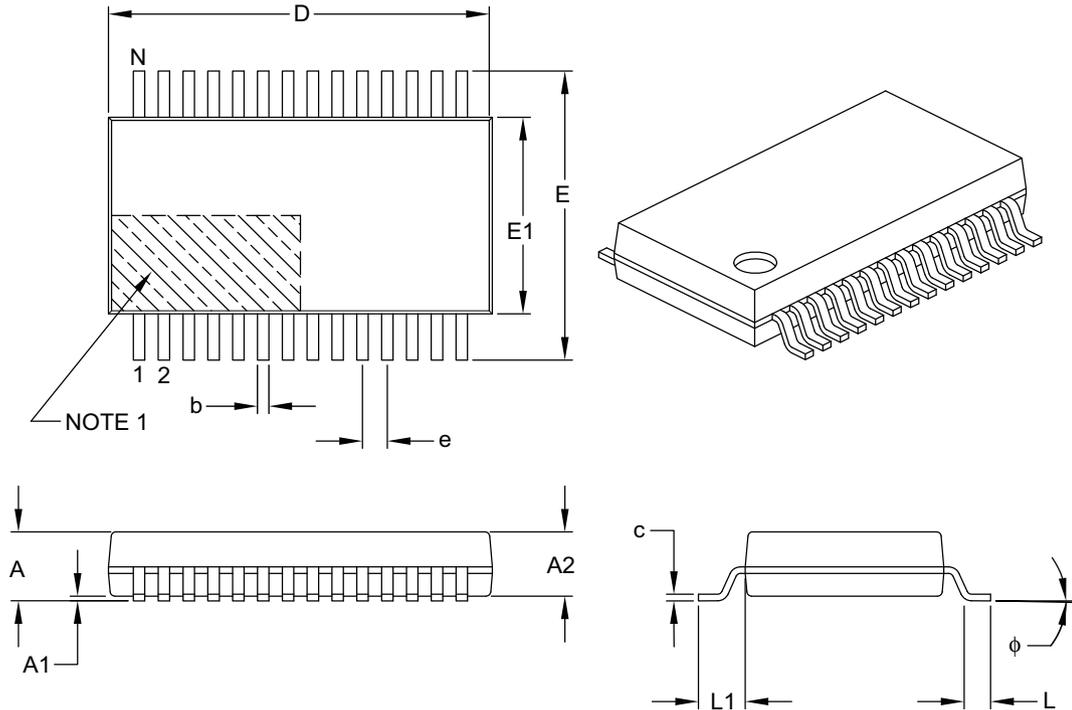
PIC32MX1XX/2XX 28/36/44-PIN FAMILY

33.2 Package Details

This section provides the technical details of the packages.

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1	1.25 REF		
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

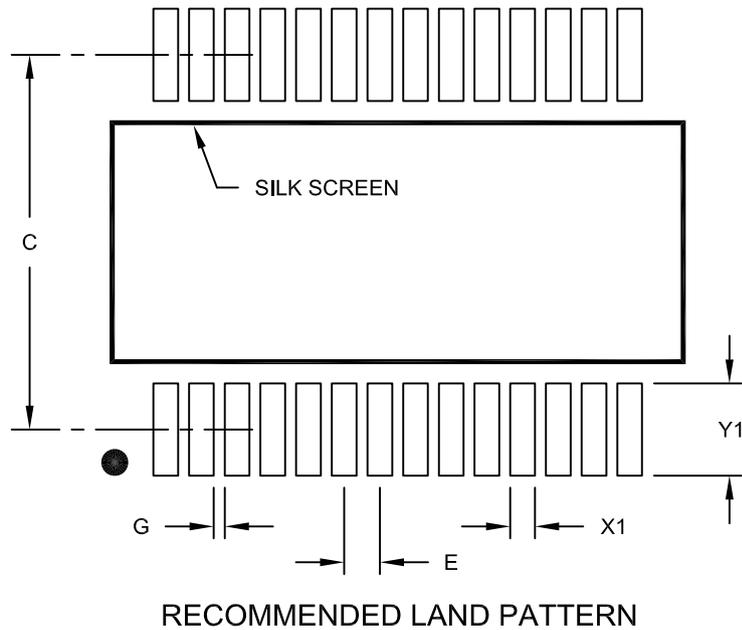
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		7.20	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

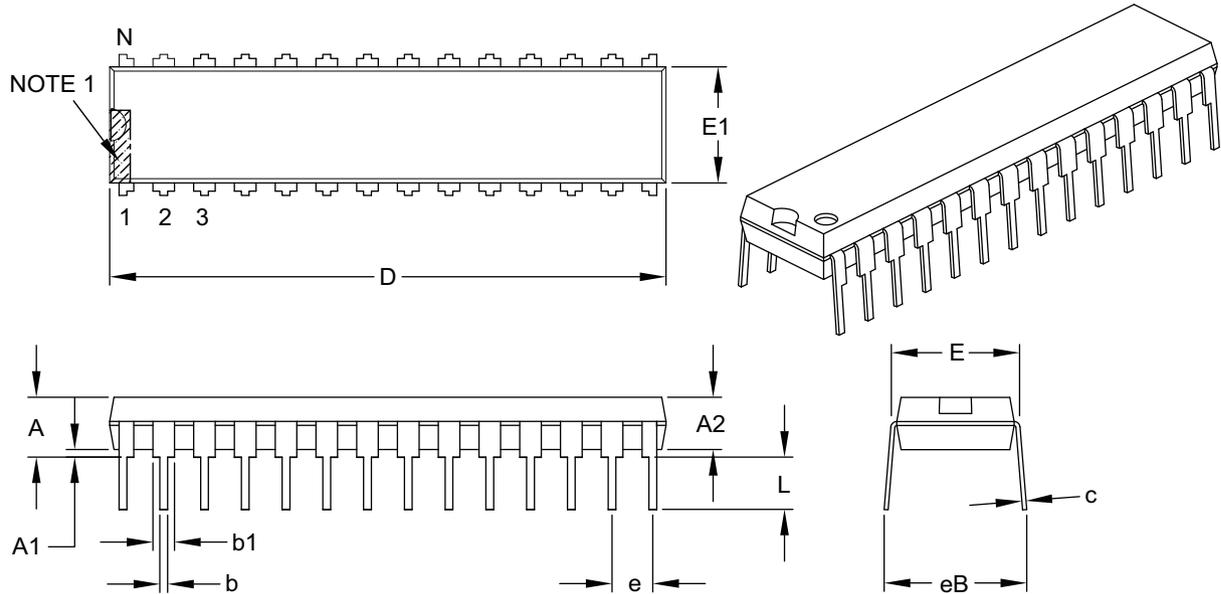
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packageing>



Dimension Limits	Units	INCHES		
		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

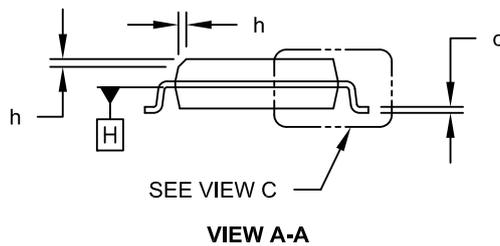
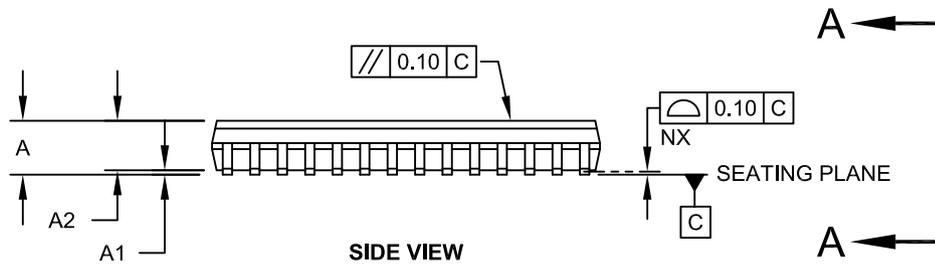
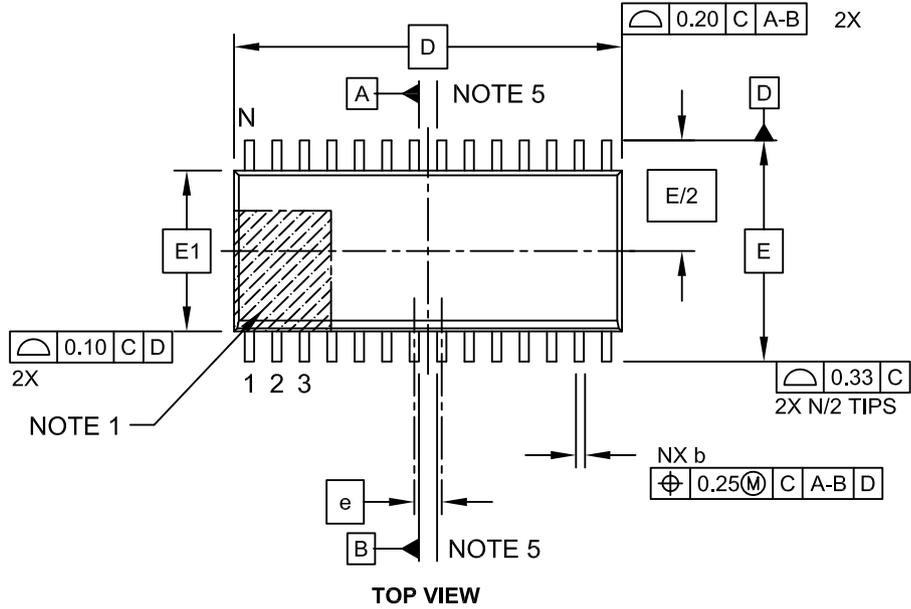
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

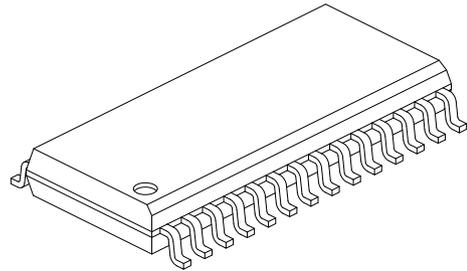
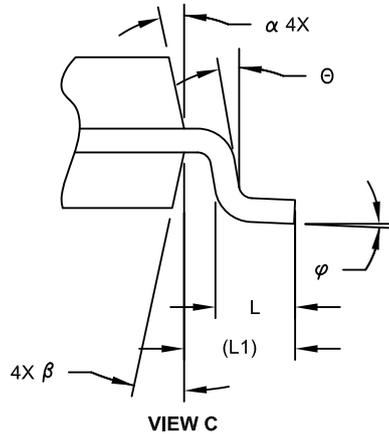


Microchip Technology Drawing C04-052C Sheet 1 of 2

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E	10.30 BSC		
Molded Package Width	E1	7.50 BSC		
Overall Length	D	17.90 BSC		
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1	1.40 REF		
Lead Angle	θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

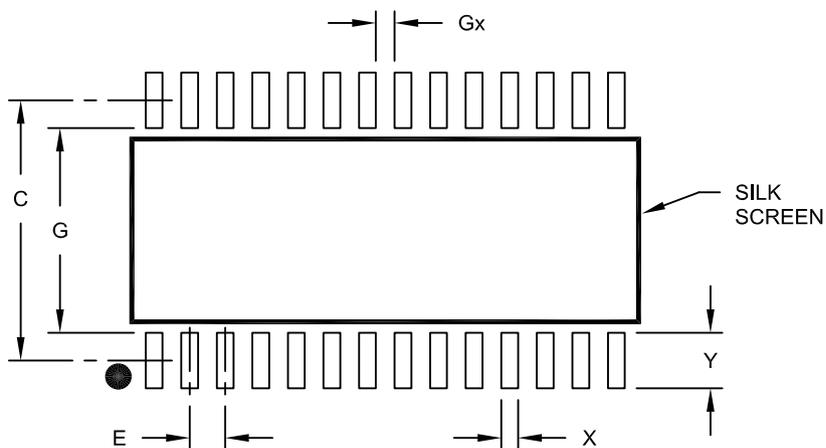
- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.
- Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

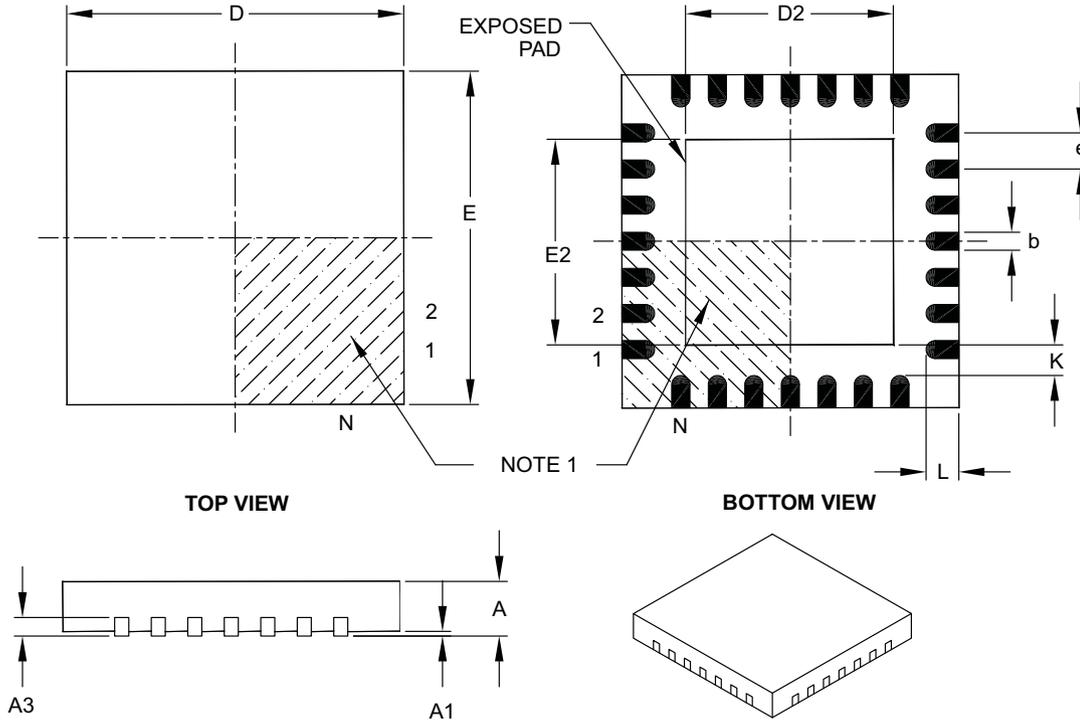
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	0.65 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3	0.20 REF		
Overall Width	E	6.00 BSC		
Exposed Pad Width	E2	3.65	3.70	4.20
Overall Length	D	6.00 BSC		
Exposed Pad Length	D2	3.65	3.70	4.20
Contact Width	b	0.23	0.30	0.35
Contact Length	L	0.50	0.55	0.70
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

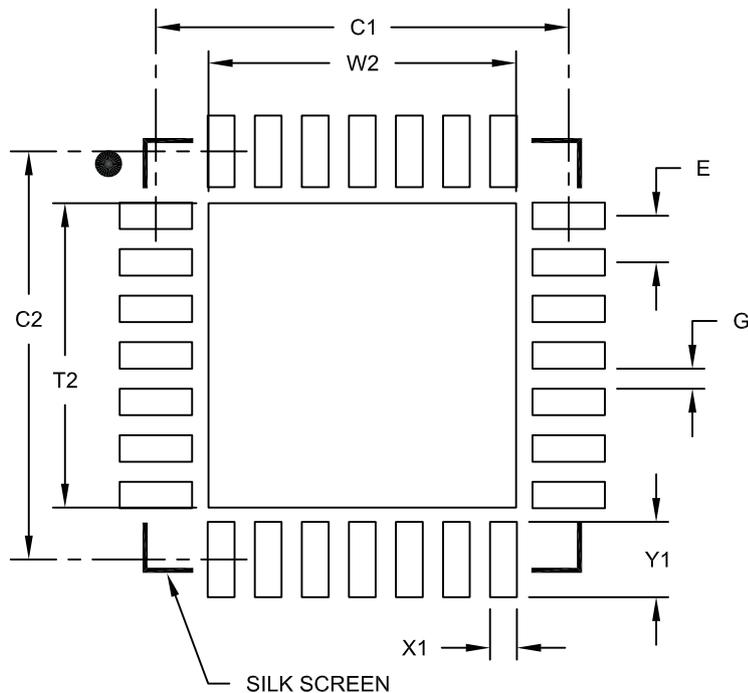
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105B

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			4.25
Optional Center Pad Length	T2			4.25
Contact Pad Spacing	C1		5.70	
Contact Pad Spacing	C2		5.70	
Contact Pad Width (X28)	X1			0.37
Contact Pad Length (X28)	Y1			1.00
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

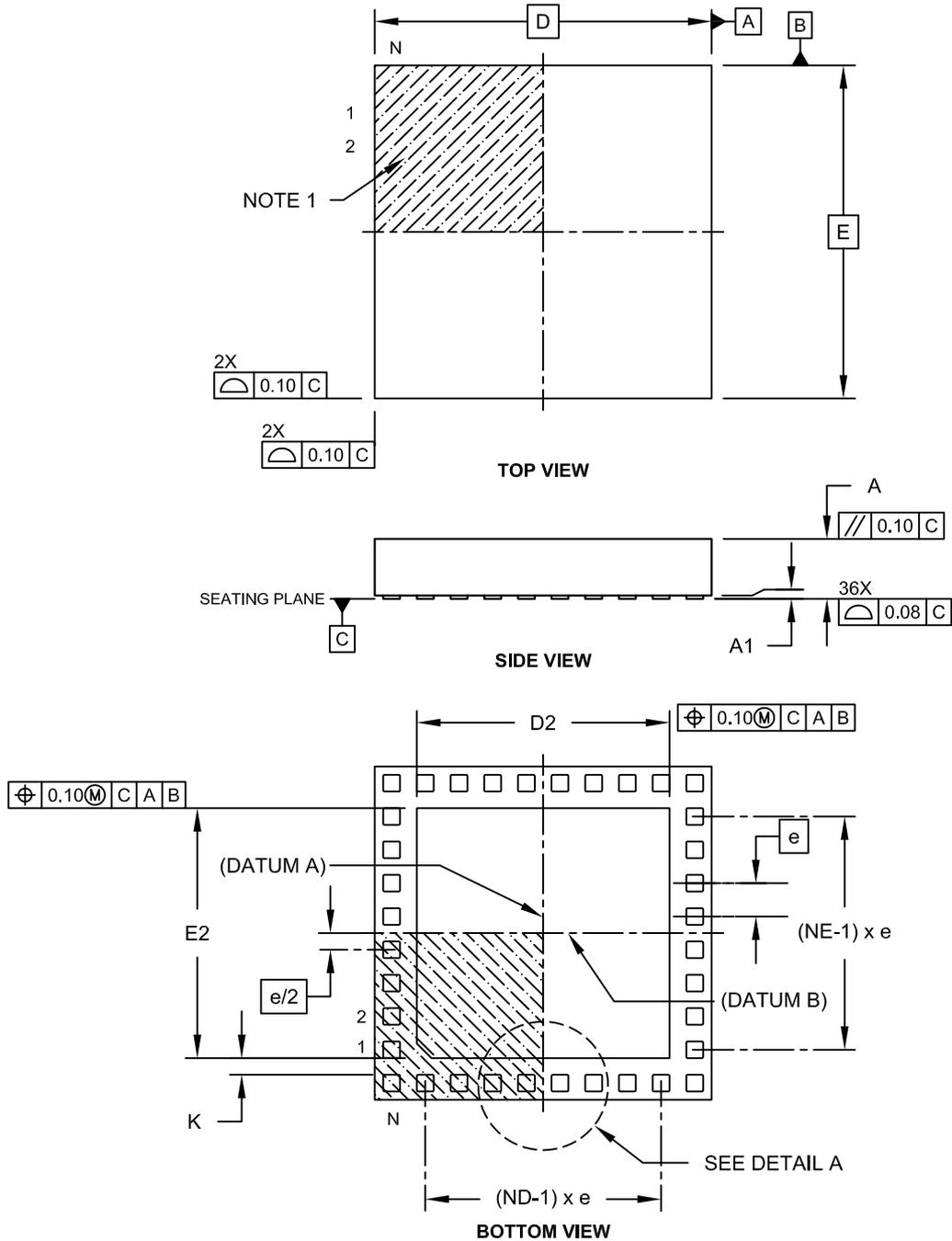
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2105A

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

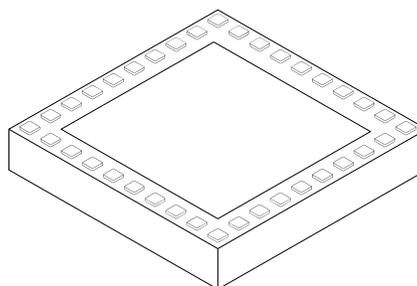
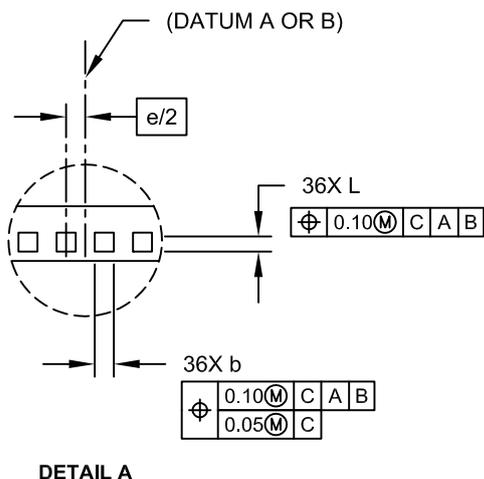


Microchip Technology Drawing C04-187C Sheet 1 of 2

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension	Units	MILLIMETERS		
	Limits	MIN	NOM	MAX
Number of Pins	N	36		
Number of Pins per Side	ND	10		
Number of Pins per Side	NE	8		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E	5.00 BSC		
Exposed Pad Width	E2	3.60	3.75	3.90
Overall Length	D	5.00 BSC		
Exposed Pad Length	D2	3.60	3.75	3.90
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

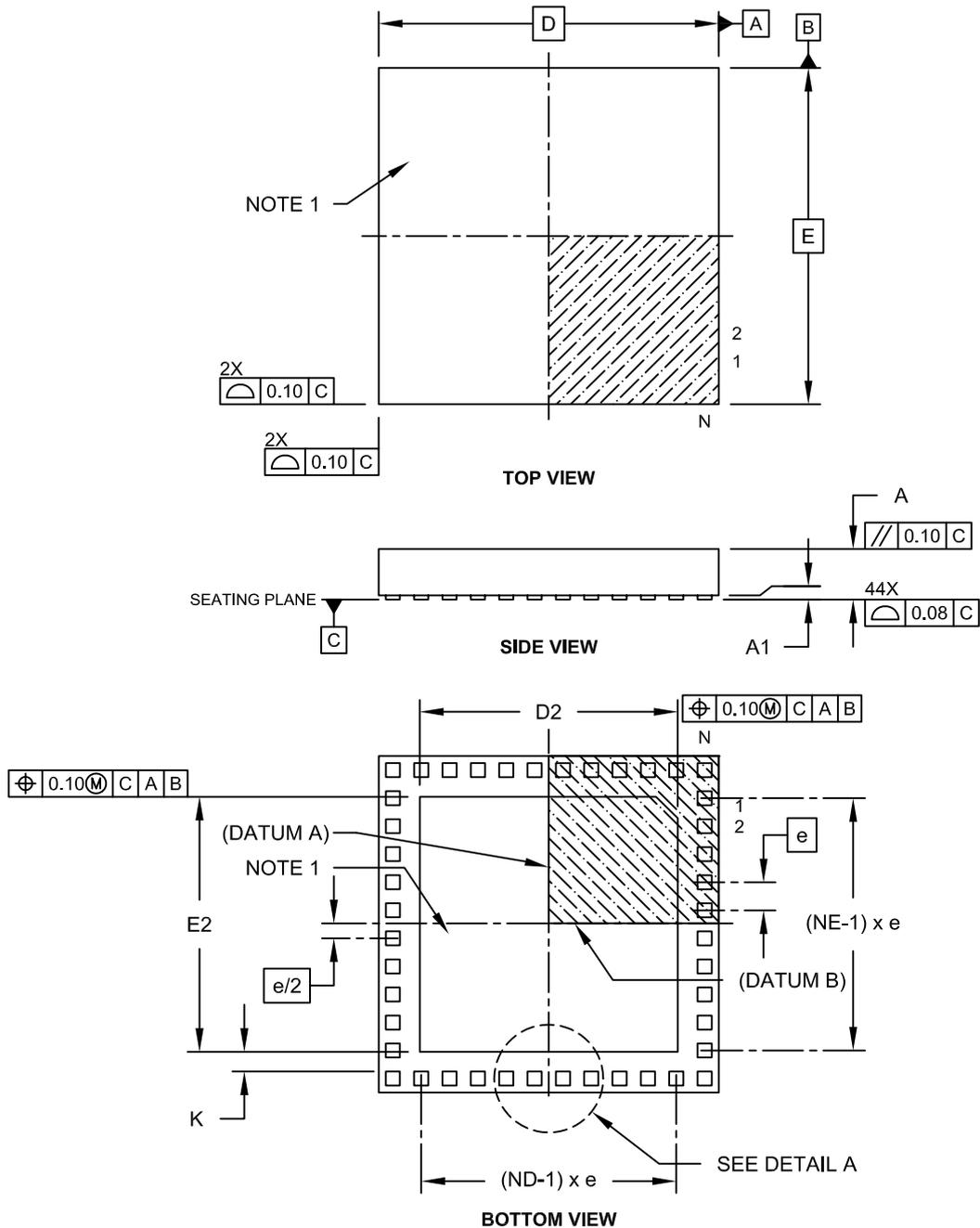
- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-187C Sheet 2 of 2

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

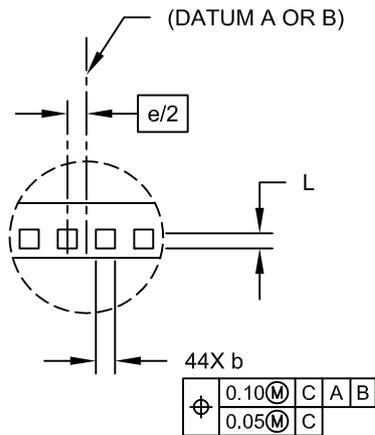


Microchip Technology Drawing C04-157C Sheet 1 of 2

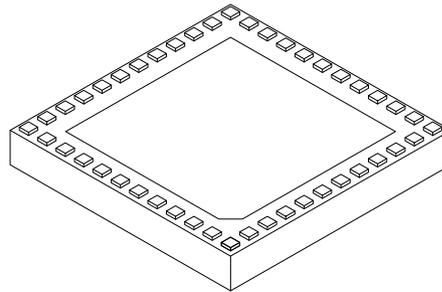
PIC32MX1XX/2XX 28/36/44-PIN FAMILY

44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



DETAIL A



Dimension	Units	MILLIMETERS		
	Limits	MIN	NOM	MAX
Number of Pins	N		44	
Number of Pins per Side	ND		12	
Number of Pins per Side	NE		10	
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E	6.00 BSC		
Exposed Pad Width	E2	4.40	4.55	4.70
Overall Length	D	6.00 BSC		
Exposed Pad Length	D2	4.40	4.55	4.70
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

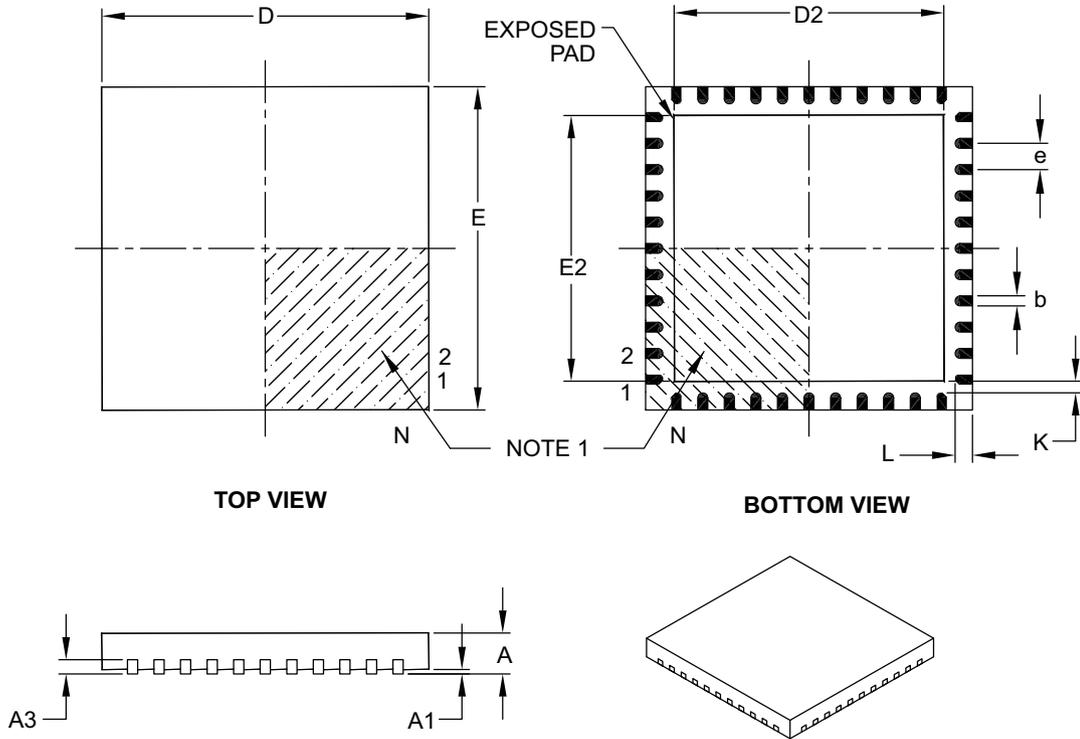
- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-157C Sheet 2 of 2

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packages>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	44		
Pitch	e	0.65 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3	0.20 REF		
Overall Width	E	8.00 BSC		
Exposed Pad Width	E2	6.30	6.45	6.80
Overall Length	D	8.00 BSC		
Exposed Pad Length	D2	6.30	6.45	6.80
Contact Width	b	0.25	0.30	0.38
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

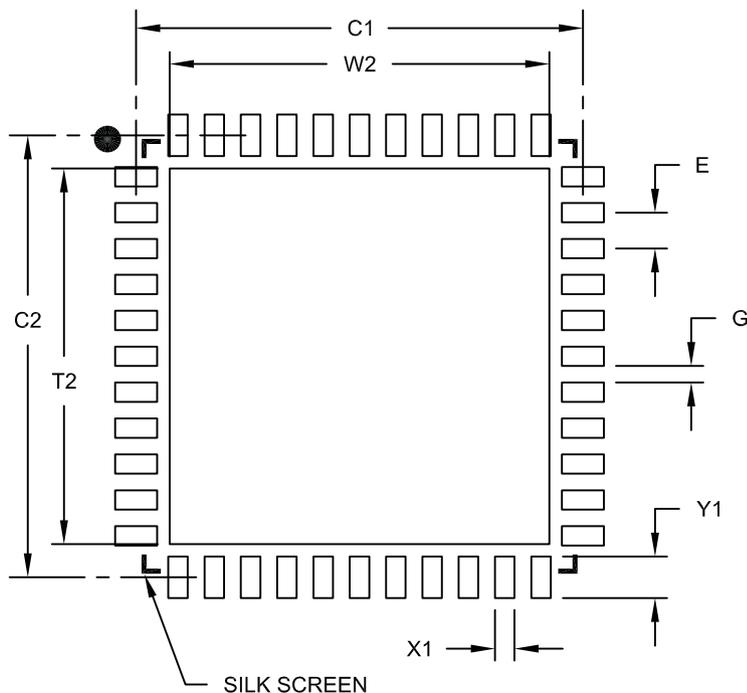
- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103B

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
		MIN	NOM	MAX
	Dimension Limits			
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			6.80
Optional Center Pad Length	T2			6.80
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.80
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

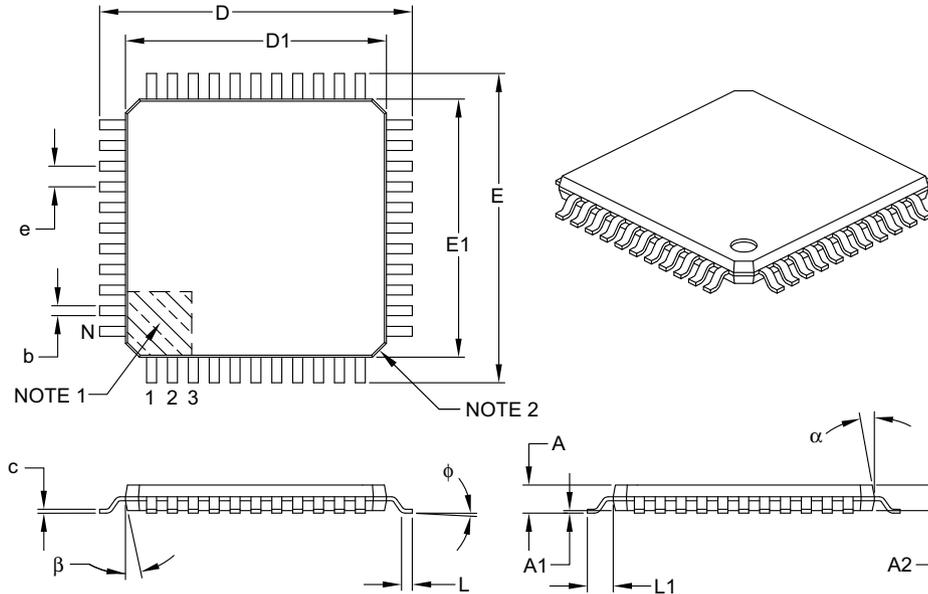
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103A

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Leads	N		44		
Lead Pitch	e		0.80 BSC		
Overall Height	A		–	–	1.20
Molded Package Thickness	A2		0.95	1.00	1.05
Standoff	A1		0.05	–	0.15
Foot Length	L		0.45	0.60	0.75
Footprint	L1		1.00 REF		
Foot Angle	φ		0°	3.5°	7°
Overall Width	E		12.00 BSC		
Overall Length	D		12.00 BSC		
Molded Package Width	E1		10.00 BSC		
Molded Package Length	D1		10.00 BSC		
Lead Thickness	c		0.09	–	0.20
Lead Width	b		0.30	0.37	0.45
Mold Draft Angle Top	α		11°	12°	13°
Mold Draft Angle Bottom	β		11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

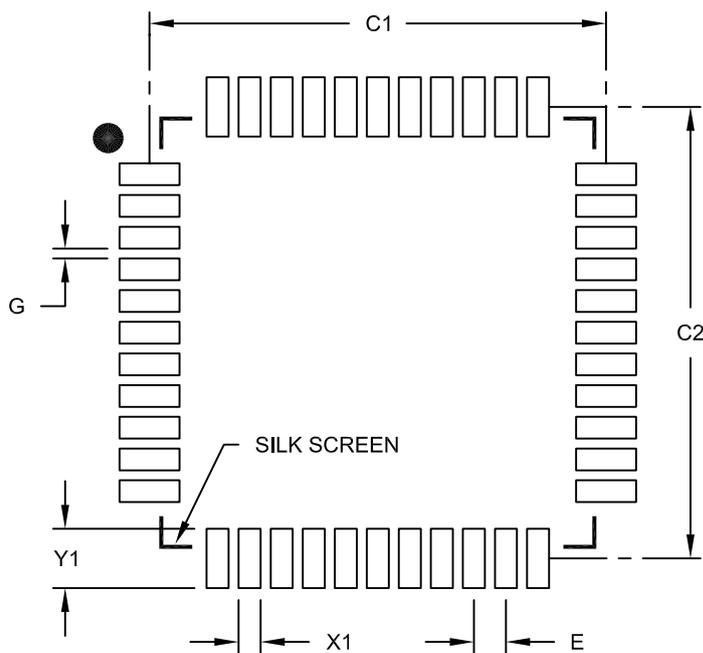
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

44-Lead Plastic Thin Quad Flatpack (PT) 10X10X1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.80 BSC		
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X44)	X1			0.55
Contact Pad Length (X44)	Y1			1.50
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076B

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

APPENDIX A: REVISION HISTORY

Revision A (May 2011)

This is the initial released version of this document.

Revision B (October 2011)

The following two global changes are included in this revision:

- All packaging references to VLAP have been changed to VTLA throughout the document
- All references to VCORE have been removed
- All occurrences of the ASCL1, ASCL2, ASDA1, and ASDA2 pins have been removed
- V-temp temperature range (-40°C to +105°C) was added to all electrical specification tables

This revision includes the addition of the following devices:

- PIC32MX130F064B
- PIC32MX130F064C
- PIC32MX130F064D
- PIC32MX150F128B
- PIC32MX150F128C
- PIC32MX150F128D
- PIC32MX230F064B
- PIC32MX230F064C
- PIC32MX230F064D
- PIC32MX250F128B
- PIC32MX250F128C
- PIC32MX250F128D

Text and formatting changes were incorporated throughout the document.

All other major changes are referenced by their respective section in [Table A-1](#).

TABLE A-1: MAJOR SECTION UPDATES

Section	Update Description
“32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog”	<p>Split the existing Features table into two: PIC32MX1XX General Purpose Family Features (Table 1) and PIC32MX2XX USB Family Features (Table 2).</p> <p>Added the SPDIP package reference (see Table 1, Table 2, and “Pin Diagrams”).</p> <p>Added the new devices to the applicable pin diagrams.</p> <p>Changed PGED2 to PGED1 on pin 35 of the 36-pin VTLA diagram for PIC32MX220F032C, PIC32MX220F016C, PIC32MX230F064C, and PIC32MX250F128C devices.</p>
1.0 “Device Overview”	<p>Added the SPDIP package reference and updated the pin number for AN12 for 44-pin QFN devices in the Pinout I/O Descriptions (see Table 1-1).</p> <p>Added the PGEC4/PGED4 pin pair and updated the C1INA-C1IND and C2INA-C2IND pin numbers for 28-pin SSOP/SPDIP/SOIC devices in the Pinout I/O Descriptions (see Table 1-1).</p>
2.0 “Guidelines for Getting Started with 32-bit Microcontrollers”	<p>Updated the Recommended Minimum Connection diagram (see Figure 2-1).</p>

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section	Update Description
4.0 “Memory Organization”	<p>Added Memory Maps for the new devices (see Figure 4-3 and Figure 4-4).</p> <p>Removed the BMXCHEDMA bit from the Bus Matrix Register map (see Table 4-1).</p> <p>Added the REFOTRIM register, added the DIVSWEN bit to the REFOCON registers, added Note 4 to the ULOCK and SOSSEN bits and added the PBDIVRDY bit in the OSCCON register in the in the System Control Register map (see Table 4-16).</p> <p>Removed the ALTI2C1 and ALTI2C2 bits from the DEVCFG3 register and added Note 1 to the UPLEN and UPLLIDIV<2:0> bits of the DEVCFG2 register in the Device Configuration Word Summary (see Table 4-17).</p> <p>Updated Note 1 in the Device and Revision ID Summary (see Table 4-18).</p> <p>Added Note 2 to the PORTA Register map (see Table 4-19).</p> <p>Added the ANSB6 and ANSB12 bits to the ANSELB register in the PORTB Register map (see Table 4-20).</p> <p>Added Notes 2 and 3 to the PORTC Register map (see Table 4-21).</p> <p>Updated all register names in the Peripheral Pin Select Register map (see Table 4-23).</p> <p>Added values in support of new devices (16 KB RAM and 32 KB RAM) in the Data RAM Size register (see Register 4-5).</p> <p>Added values in support of new devices (64 KB Flash and 128 KB Flash) in the Data RAM Size register (see Register 4-5).</p>
8.0 “Oscillator Configuration”	<p>Added Note 5 to the PIC32MX1XX/2XX Family Clock Diagram (see Figure 8-1).</p> <p>Added the PBDIVRDY bit and Note 2 to the Oscillator Control register (see Register 8-1).</p> <p>Added the DIVSWEN bit and Note 3 to the Reference Oscillator Control register (see Register 8-3).</p> <p>Added the REFOTRIM register (see Register 8-4).</p>
21.0 “10-bit Analog-to-Digital Converter (ADC)”	<p>Updated the ADC1 Module Block Diagram (see Figure 21-1).</p> <p>Updated the Notes in the ADC Input Select register (see Register 21-4).</p>
24.0 “Charge Time Measurement Unit (CTMU)”	<p>Updated the CTMU Block Diagram (see Figure 24-1).</p> <p>Added Note 3 to the CTMU Control register (see Register 24-1)</p>
26.0 “Special Features”	<p>Added Note 1 and the PGEC4/PGED4 pin pair to the ICESSEL<1:0> bits in DEVCFG0: Device Configuration Word 0 (see Register 26-1).</p> <p>Removed the ALTI2C1 and ALTI2C2 bits from the Device Configuration Word 3 register (see Register 26-4).</p> <p>Removed 26.3.3 “Power-up Requirements”.</p> <p>Added Note 3 to the Connections for the On-Chip Regulator diagram (see Figure 26-2).</p> <p>Updated the Block Diagram of Programming, Debugging and Trace Ports diagram (see Figure 26-3).</p>

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TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section	Update Description
29.0 “Electrical Characteristics”	<p>Updated the Absolute Maximum Ratings (removed Voltage on V_{CORE} with respect to V_{SS}).</p> <p>Added the SPDIP specification to the Thermal Packaging Characteristics (see Table 29-2).</p> <p>Updated the Typical values for parameters DC20-DC24 in the Operating Current (I_{DD}) specification (see Table 29-5).</p> <p>Updated the Typical values for parameters DC30a-DC34a in the Idle Current (I_{IDLE}) specification (see Table 29-6).</p> <p>Updated the Typical values for parameters DC40i and DC40n and removed parameter DC40m in the Power-down Current (I_{PD}) specification (see Table 29-7).</p> <p>Removed parameter D320 (V_{CORE}) from the Internal Voltage Regulator Specifications and updated the Comments (see Table 29-13).</p> <p>Updated the Minimum, Typical, and Maximum values for parameter F20b in the Internal FRC Accuracy specification (see Table 29-17).</p> <p>Removed parameter SY01 (TPWRT) and removed all Conditions from Resets Timing (see Table 29-20).</p> <p>Updated all parameters in the CTMU Specifications (see Table 29-39).</p>
31.0 “Packaging Information”	Added the 28-lead SPDIP package diagram information (see 31.1 “Package Marking Information” and 31.2 “Package Details”).
“Product Identification System”	Added the SPDIP (SP) package definition.

Revision C (November 2011)

All major changes are referenced by their respective section in [Table A-2](#).

TABLE A-2: MAJOR SECTION UPDATES

Section	Update Description
“32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog”	<p>Revised the source/sink on I/O pins (see “Input/Output” on page 1).</p> <p>Added the SPDIP package to the PIC32MX220F032B device in the PIC32MX2XX USB Family Features (see Table 2).</p>
4.0 “Memory Organization”	Removed ANSB6 from the ANSELB register and added the ODCB6, ODCB10, and ODCB11 bits in the PORTB Register Map (see Table 4-20).
29.0 “Electrical Characteristics”	Updated the minimum value for parameter OS50 in the PLL Clock Timing Specifications (see Table 29-16).

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Revision D (February 2012)

All occurrences of VUSB were changed to: VUSB3V3. In addition, text and formatting changes were incorporated throughout the document.

All other major changes are referenced by their respective section in [Table A-3](#).

TABLE A-3: MAJOR SECTION UPDATES

Section	Update Description
“32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog”	Corrected a part number error in all pin diagrams. Updated the DMA Channels (Programmable/Dedicated) column in the PIC32MX1XX General Purpose Family Features (see Table 1).
1.0 “Device Overview”	Added the TQFP and VTLA packages to the 44-pin column heading and updated the pin numbers for the SCL1, SCL2, SDA1, and SDA2 pins in the Pinout I/O Descriptions (see Table 1-1).
7.0 “Interrupt Controller”	Updated the Note that follows the features. Updated the Interrupt Controller Block Diagram (see Figure 7-1).
29.0 “Electrical Characteristics”	Updated the Maximum values for parameters DC20-DC24, and the Minimum value for parameter DC21 in the Operating Current (IDD) DC Characteristics (see Table 29-5). Updated all Minimum and Maximum values for the Idle Current (IIDL) DC Characteristics (see Table 29-6). Updated the Maximum values for parameters DC40k, DC40l, DC40n, and DC40m in the Power-down Current (IPD) DC Characteristics (see Table 29-7). Changed the minimum clock period for SCKx from 40 ns to 50 ns in Note 3 of the SPIx Master and Slave Mode Timing Requirements (see Table 29-26 through Table 29-29).
30.0 “DC and AC Device Characteristics Graphs”	Updated the Typical IIDL Current @ VDD = 3.3V graph (see Figure 30-5).

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Revision E (October 2012)

All singular pin diagram occurrences of CVREF were changed to: CVREFOUT. In addition, minor text and formatting changes were incorporated throughout the document.

All major changes are referenced by their respective section in [Table A-4](#).

TABLE A-4: MAJOR SECTION UPDATES

Section	Update Description
“32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog”	Updated the following feature sections: <ul style="list-style-type: none">• “Operating Conditions”• “Communication Interfaces”
2.0 “Guidelines for Getting Started with 32-bit MCUs”	Removed Section 2.8 “Configuration of Analog and Digital Pins During ICSP Operations”.
3.0 “CPU”	Removed references to GPR shadow registers in 3.1 “Features” and 3.2.1 “Execution Unit” .
4.0 “Memory Organization”	Updated the BRG bit range in the SPI1 and SPI2 Register Map (see Table 4-8). Added the PWP<6> bit to the Device Configuration Word Summary (see Table 4-17).
5.0 “Flash Program Memory”	Added a note with Flash page size and row size information.
7.0 “Interrupt Controller”	Updated the TPC<2:0> bit definitions (see Register 7-1). Updated the IPTMR<31:0> bit definition (see Register 7-3).
8.0 “Oscillator Configuration”	Updated the PIC32MX1XX/2XX Family Clock Diagram (see Figure 8-1). Updated the RODIV<14:0> bit definitions (see Register 8-3).
10.0 “USB On-The-Go (OTG)”	Updated the Notes in the USB Interface Diagram (see Figure 10-1).
18.0 “Universal Asynchronous Receiver Transmitter (UART)”	Updated the baud rate range in the list of primary features.
26.0 “Special Features”	Added the PWP<6> bit to the Device Configuration Word 0 (see Register 26-1).
29.0 “Electrical Characteristics”	Added Note 1 to Operating MIPS vs. Voltage (see Table 29-1). Added Note 2 to DC Temperature and Voltage Specifications (see Table 29-4). Updated the Conditions for parameter DC25 in DC Characteristics: Operating Current (IDD) (see Table 29-5). Added Note 2 to Electrical Characteristics: BOR (see Table 29-10). Added Note 4 to Comparator Specifications (see Table 29-12). Added Note 5 to ADC Module Specifications (see Table 29-32). Updated the 10-bit Conversion Rate Parameters and added Note 3 (see Table 29-33). Added Note 4 to the Analog-to-Digital Conversion Timing Requirements (see Table 29-34). Added Note 3 to CTMU Current Source Specifications (see Table 29-39).
30.0 “50 MHz Electrical Characteristics”	New chapter with electrical characteristics for 50 MHz devices.
31.0 “Packaging Information”	The 36-pin and 44-pin VTLA packages have been updated.

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Revision F (February 2014)

This revision includes the addition of the following devices:

- PIC32MX170F256B
- PIC32MX270F256B
- PIC32MX170F256D
- PIC32MX270F256D

In addition, this revision includes the following major changes as described in [Table A-5](#), as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-5: MAJOR SECTION UPDATES

Section	Update Description
32-bit Microcontrollers (up to 256 KB Flash and 64 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog	Added new devices to the family features (see Table 1 and Table 2). Updated pin diagrams to include new devices (see “ Pin Diagrams ”).
1.0 “Device Overview”	Added Note 3 reference to the following pin names: VBUS, VUSB3V3, VBUSON, D+, D-, and USBID.
2.0 “Guidelines for Getting Started with 32-bit MCUs”	Replaced Figure 2-1: Recommended Minimum Connection. Updated Figure 2-2: MCLR Pin Connections. Added 2.9 “Sosc Design Recommendation” .
4.0 “Memory Organization”	Added memory tables for devices with 64 KB RAM (see Table 4-4 through Table 4-5). Changed the Virtual Addresses for all registers and updated the PWP bits in the DEVCFG: Device Configuration Word Summary (see Table 4-17). Updated the ODCA, ODCB, and ODCC port registers (see Table 4-19, Table 4-20, and Table 4-21). The RTCTIME, RTCDATE, ALRMTIME, and ALRMDATE registers were updated (see Table 4-25). Added Data Ram Size value for 64 KB RAM devices (see Register 4-5). Added Program Flash Size value for 256 KB Flash devices (see Register 4-5).
12.0 “Timer1”	The Timer1 block diagram was updated to include the 16-bit data bus (see Figure 12-1).
13.0 “Timer2/3, Timer4/5”	The Timer2-Timer5 block diagram (16-bit) was updated to include the 16-bit data bus (see Figure 13-1). The Timer2/3, Timer4/5 block diagram (32-bit) was updated to include the 32-bit data bus (see Figure 13-1).
19.0 “Parallel Master Port (PMP)”	The CSF<1:0> bit value definitions for ‘00’ and ‘01’ were updated (see Register 19-1). Bit 14 in the Parallel Port Address register (PMADDR) was updated (see Register 19-3).
20.0 “Real-Time Clock and Calendar (RTCC)”	The following registers were updated: RTCTIME (see Register 20-3) RTCDATE (see Register 20-4) ALRMTIME (see Register 20-5) ALRMDATE (see Register 20-6)
26.0 “Special Features”	Updated the PWP bits (see Register 26-1).
29.0 “Electrical Characteristics”	Added parameters DO50 and DO50a to the Capacitive Loading Requirements on Output Pins (see Table 29-14). Added Note 5 to the IDD DC Characteristics (see Table 29-5). Added Note 4 to the IDLE DC Characteristics (see Table 29-6). Added Note 5 to the IPD DC Characteristics (see Table 29-7). Updated the conditions for parameters USB321 (VOL) and USB322 (VOH) in the OTG Electrical Specifications (see Table 29-38).
Product Identification System	Added 40 MHz speed information.

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Revision G (April 2015)

This revision includes the addition of the following devices:

- PIC32MX130F256B
- PIC32MX230F256B
- PIC32MX130F256D
- PIC32MX230F256D

The title of the document was updated to avoid confusion with the PIC32MX1XX/2XX/5XX 64/100-pin Family data sheet.

All peripheral SFR maps have been relocated from the Memory chapter to their respective peripheral chapters.

In addition, this revision includes the following major changes as described in [Table A-6](#), as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-6: MAJOR SECTION UPDATES

Section	Update Description
32-bit Microcontrollers (up to 256 KB Flash and 64 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog	Added new devices to the family features (see Table 1 and Table 2). Updated pin diagrams to include new devices (see Pin Diagrams).
2.0 “Guidelines for Getting Started with 32-bit MCUs”	Updated these sections: 2.2 “Decoupling Capacitors” , 2.3 “Capacitor on Internal Voltage Regulator (VCAP)” , 2.4 “Master Clear (MCLR) Pin” , 2.8.1 “Crystal Oscillator Design Consideration”
4.0 “Memory Organization”	Added Memory Map for new devices (see Figure 4-6).
14.0 “Watchdog Timer (WDT)”	New chapter created from content previously located in the Special Features chapter.
30.0 “Electrical Characteristics”	Removed parameter D312 (TSET) from the Comparator Specifications (see Table 30-12). Added the Comparator Voltage Reference Specifications (see Table 30-13). Updated Table 30-12.

Revision H (July 2015)

This revision includes the following major changes as described in [Table A-7](#), as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-7: MAJOR SECTION UPDATES

Section	Update Description
2.0 “Guidelines for Getting Started with 32-bit MCUs”	Section 2.9 “Sosc Design Recommendation” was removed.
8.0 “Oscillator Configuration”	The Primary Oscillator (Posc) logic in the Oscillator diagram was updated (see Figure 8-1).
30.0 “Electrical Characteristics”	The Power-Down Current (IPD) DC Characteristics parameter DC40k was updated (see Table 30-7). Table 30-9: “DC Characteristics: I/O Pin Input Injection current Specifications” was added.

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Revision J (April 2016)

This revision includes the following major changes as described in [Table A-8](#), as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-8: MAJOR SECTION UPDATES

Section	Update Description
“32-bit Microcontrollers (up to 256 KB Flash and 64 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog”	The PIC32MX270FDB device and Note 4 were added to TABLE 2: “PIC32MX2XX 28/36/44-pin USB Family Features” .
2.0 “Guidelines for Getting Started with 32-bit MCUs”	EXAMPLE 2-1: “Crystal Load Capacitor Calculation” was updated.
30.0 “Electrical Characteristics”	Parameter DO50a (Csosc) was removed from the Capacitive Loading Requirements on Output Pins AC Characteristics (see Table 30-16).
“Product Identification System”	The device mapping was updated to include type B for Software Targeting.

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PIC32MX1XX/2XX 28/36/44-PIN FAMILY

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

	PIC32 MX 1XX F 032 D B T - 50 I / PT - XXX	
Microchip Brand	_____	Example: PIC32MX110F032DT-I/PT: General purpose PIC32, 32-bit RISC MCU with M4K® core, 32 KB program memory, 44-pin, Industrial temperature, TQFP package.
Architecture	_____	
Product Groups	_____	
Flash Memory Family	_____	
Program Memory Size (KB)	_____	
Pin Count	_____	
Software Targeting	_____	
Tape and Reel Flag (if applicable)	_____	
Speed (if applicable)	_____	
Temperature Range	_____	
Package	_____	
Pattern	_____	
Flash Memory Family		
Architecture	MX = M4K® MCU core	
Product Groups	1XX = General purpose microcontroller family 2XX = General purpose microcontroller family	
Flash Memory Family	F = Flash program memory	
Program Memory Size	016 = 16K 032 = 32K 064 = 64K 128 = 128K 256 = 256K	
Pin Count	B = 28-pin C = 36-pin D = 44-pin	
Software Targeting	B = Targeted for Bluetooth® Audio Break-in devices	
Speed	() = 40 MHz – () indicates a blank field; package markings for 40 MHz devices do not include the Speed 50 = 50 MHz	
Temperature Range	I = -40°C to +85°C (Industrial) V = -40°C to +105°C (V-temp)	
Package	ML = 28-Lead (6x6 mm) QFN (Plastic Quad Flatpack) ML = 44-Lead (8x8 mm) QFN (Plastic Quad Flatpack) PT = 44-Lead (10x10x1 mm) TQFP (Plastic Thin Quad Flatpack) SO = 28-Lead (7.50 mm) SOIC (Plastic Small Outline) SP = 28-Lead (300 mil) SPDIP (Skinny Plastic Dual In-line) SS = 28-Lead (5.30 mm) SSOP (Plastic Shrink Small Outline) TL = 36-Lead (5x5 mm) VTLA (Very Thin Leadless Array) TL = 44-Lead (6x6 mm) VTLA (Very Thin Leadless Array)	
Pattern	Three-digit QTP, SQTP, Code or Special Requirements (blank otherwise) ES = Engineering Sample	

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Факс: +7 495 668-12-70 (доб.304)

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